8-bit Microcontrollers

CMOS

F²MC-8FX MB95130MB Series

MB95136MB/F133MBS/F133NBS/F133JBS/F134MBS/F134NBS/F134JBS/MB95F136MBS/F136NBS/F136JBS/F133MBW/F133NBW/F133JBW/F134MBW/MB95F134NBW/F134JBW/F136MBW/F136NBW/F136JBW/FV100D-103

■ DESCRIPTION

The MB95130MB series is general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions.

Note: F²MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURES

- F2MC-8FX CPU core
 - Instruction set optimized for controllers
 - · Multiplication and division instructions
 - 16-bit arithmetic operations
 - · Bit test branch instruction
 - Bit manipulation instructions etc.
- Clock
 - Main clock
 - Main PLL clock
 - Sub clock (for dual clock product)
 - Sub PLL clock (for dual clock product)

(Continued)

For the information for microcontroller supports, see the following web site.

http://edevice.fujitsu.com/micom/en-support/



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(Continued)

- Timer
 - 8/16-bit compound timer × 1 channel
 - 8/16-bit PPG × 1 channel
 - 16-bit PPG × 1 channel
 - Time-base timer × 1 channel
 - Watch prescaler (for dual clock product) × 1 channel
- LIN-UART × 1 channel
 - LIN function, Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
 - Full duplex double buffer
- UART/SIO × 1 channel
 - · Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
 - Full duplex double buffer
- External interrupt × 8 channels
 - Interrupt by edge detection (rising, falling, or both edges can be selected)
 - Can be used to recover from low-power consumption (standby) modes.
- 8/10-bit A/D converter × 8 channels
 - 8-bit or 10-bit resolution can be selected.
- Low-power consumption (standby) mode
 - Stop mode
 - · Sleep mode
 - Watch mode (for dual clock product)
 - Time-base timer mode
- I/O port
 - The number of maximum ports
 - Single clock product : 19 ports
 - Dual clock product : 17 ports
 - Configuration

General-purpose I/O ports (COMS): Single clock product: 19 ports

Dual clock product : 17 ports

• Power-on reset

A power-on reset is generated when the power is switched on.

• Programmable input voltage levels of port

Automotive input level / CMOS input level / hysteresis input level

• Flash memory security function

Protects the content of Flash memory (Flash memory device only)

■ MEMORY LINEUP

	Flash memory	RAM
MB95F133MBS/F133NBS/F133JBS	8 Kbytes	256 bytes
MB95F133MBW/F133NBW/F133JBW	o Royles	230 bytes
MB95F134MBS/F134NBS/F134JBS	16 Khytaa	F12 bytes
MB95F134MBW/F134NBW/F134JBW	16 Kbytes	512 bytes
MB95F136MBS/F136NBS/F136JBS	22 Khytaa	1 Khuta
MB95F136MBW/F136NBW/F136JBW	32 Kbytes	1 Kbyte

■ PRODUCT LINEUP

Pa	Part number	MB95136MB	MB95 F133MBS/ F134MBS/ F136MBS	MB95 F133NBS/ F134NBS/ F136NBS	MB95 F133MBW/ F134MBW/ F136MBW	MB95 F133NBW/ F134NBW/ F136NBW	MB95 F133JBS/ F134JBS/ F136JBS	MB95 F133JBW/ F134JBW/ F136JBW	
Ту	rpe	MASK ROM product		Flash memory product					
R	OM capacity*1	product		3	2 Kbytes (Max)			
	RAM capacity*1 1 Kbyte (Max)								
Po	Power-on reset Yes								
Re	eset output	Not selectable*2		Y	es		N	О	
72	Clock system	Selectable single/dual clock*3	Single	e clock	Dual	clock	Single clock	Dual clock	
Option	Low voltage detection reset	Yes/No	No	Yes	No		Yes		
	Clock supervisor	Yes/No	No Yes					es	
Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8, and 16 bits Minimum instruction execution time : 61.5 ns (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine clock frequency 16 interrupt processing time : 0.6 µs (at machine cloc									
	General-	Dual clock Programmab		orts e levels of por	t : ut level / hyster	esis input leve	ıl		
St	(1 channel)			ns, 8.2 ms, 32.	8 ms (at main	oscillation clo	ck 4 MHz)		
≠	timer	At sub oscilla	lation clock 10 tion clock 32.	768 kHz (for dı	ual clock produ	: Min 105 act) : Min 250	-		
era	Wild register			es of ROM data	a				
Periph	UART/SIO (1 channel)	Full duplex de NRZ type tra LSB-first or N	Data transfer capable in UART/SIO Full duplex double buffer, variable data length (5/6/7/8-bit), built-in baud rate generator NRZ type transfer format, error detected function LSB-first or MSB-first can be selected. Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable						
	Dedicated reload timer allowing a wide range of communication speeds to be set. LIN-UART (1 channel) Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable LIN functions available as the LIN master or LIN slave.					e			

(Continued)

Pa	Part number	MB95136MB	MB95 F133MBS/ F134MBS/ F136MBS	MB95 F133NBS/ F134NBS/ F136NBS	MB95 F133MBW/ F134MBW/ F136MBW	MB95 F133NBW/ F134NBW/ F136NBW	MB95 F133JBS/ F134JBS/ F136JBS	MB95 F133JBW/ F134JBW/ F136JBW		
	8/10-bit A/D converter (8 channels)	8-bit or 10-bit resolution can be selected.								
	8/16-bit compound timer (1 channel)	Built-in timer fu Count clock: 7	Each channel of the timer can be used as "8-bit timer x 2 channels" or "16-bit timer x 1 channel". Built-in timer function, PWC function, PWM function, capture function and square wave-form output Count clock: 7 internal clocks and external clock can be selected.							
St	(i channei)	Counter oper Support for e	ating clock: Ei xternal trigger	start	clock sources					
nctior					B-bit PPG x 2 ch clock sources		bit PPG x 1 ch	annel".		
Peripheral functions	Watch counter (for dual clock product) (1 channel)	Count clock: Four selectable clock sources (125 ms, 250 ms, 500 ms, or 1 s) Counter value can be set from 0 to 63. (Capable of counting for 1 minute when selecting clock source 1 second and setting counter value to 60)						ecting clock		
	Watch prescaler (for dual clock product) (1 channel)	Four selectable interval times (125 ms, 250 ms, 500 ms, or 1 s)								
	External interrupt (8 channels)	Interrupt by edge detection (rising, falling, or both edges can be selected.) Can be used to recover from standby modes.								
Supports automatic programming, Embedded Algorithm Write/Erase/Erase-Suspend/Resume commands A flag indicating completion of the algorithm Number of write/erase cycles (Minimum): 10000 times Flash memory Data retention time: 20 years Erase can be performed on each block Block protection with external programming voltage Flash Security Feature for protecting the content of the Flash (MB95F136MBS/F136NBS/F136JBS/F136MBW/F136NBW/F136JBW)										
St	andby mode	Sleep, stop, v	watch (for dua	l clock produc	t), and time-ba	se timer				

^{*1 :} For ROM capacity and RAM capacity, refer to "■ MEMORY LINEUP".

Note: Part number of evaluation product in MB95130MB series is MB95FV100D-103. When using it, the MCU board (MB2146-303A-E) is required.

^{*2 :} For details of option, refer to "■ MASK OPTION".

^{*3 :} Specify clock mode when ordering MASK ROM.

■ OSCILLATION STABILIZATION WAIT TIME

The initial value of the main clock oscillation stabilization wait time is fixed to the maximum value. The maximum value is shown below.

Oscillation stabilization wait time	Remarks
(2 ¹⁴ -2) /Fcн	Approx. 4.10 ms (at main oscillation clock 4 MHz)

■ PACKAGES AND CORRESPONDING PRODUCTS

Part number	MB95136MB	MB95F133MBS MB95F133NBS MB95F134MBS MB95F134NBS MB95F136MBS MB95F136NBS MB95F133JBS MB95F134JBS MB95F136JBS	MB95F133MBW MB95F133NBW MB95F134MBW MB95F134NBW MB95F136MBW MB95F136NBW MB95F133JBW MB95F134JBW MB95F136JBW	MB95FV100D-103
FPT-28P-M17	0	0	0	×
FPT-30P-M02	0	0	0	×
BGA-224P-M08	×	×	×	0

○ : Available× : Unavailable

■ DIFFERENCES AMONG PRODUCTS AND NOTES ON SELECTING PRODUCTS

• Notes on using evaluation products

The Evaluation product has not only the functions of the MB95130MB series but also those of other products to support software development for multiple series and models of the F²MC-8FX. The I/O addresses for peripheral resources not used by the MB95130MB series are therefore access-barred. Read/write access to those access-barred addresses may cause peripheral resources supposed to be unused to operate, resulting in unexpected malfunctions of hardware or software.

Particularly, do not use word access to an odd-numbered-byte address in the prohibited areas (If such access is used, the address may be read or written unexpectedly) .

Also, as the read values of prohibited addresses on the evaluation product are different to the values on the flash memory and mask ROM products, do not use these values in the software processing.

The Evaluation product does not support the functions of some bits in single-byte registers. Read/write access to these bits does not cause hardware malfunctions. No particular precautions are required to the flash memory and mask ROM products, as they have the identical read/write operation to the evaluation products.

• Difference of memory spaces

If the amount of memory on the Evaluation product is different from that of the Flash memory or MASK ROM product, carefully check the difference in the amount of memory from the model to be actually used when developing software.

For details of memory space, refer to "
CPU CORE".

• Current consumption

- The current consumption of Flash memory product is greater than for MASK ROM product.
- For details of current consumption, refer to "

 ELECTRICAL CHARACTERISTICS".

• Package

For details of information on each package, refer to "■ PACKAGES AND CORRESPONDING PRODUCTS" and "■ PACKAGE DIMENSION".

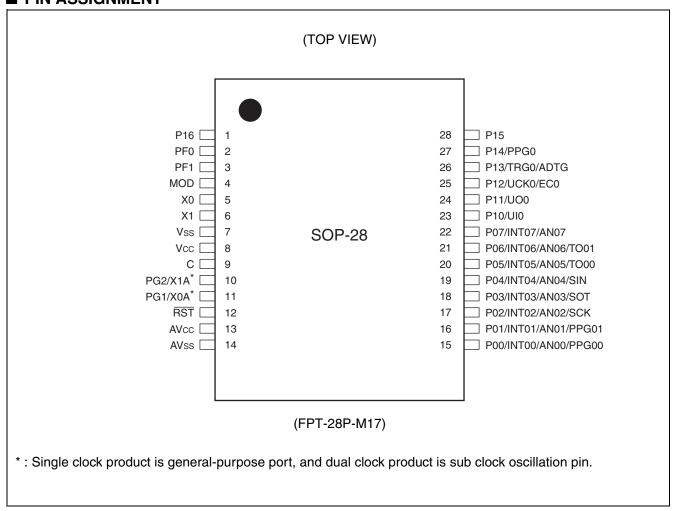
Operating voltage

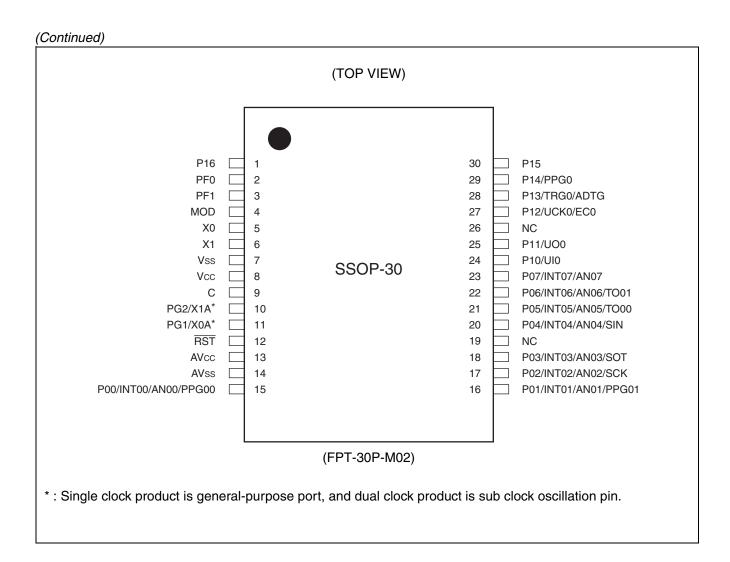
The operating voltage is different among the Evaluation, Flash memory, and MASK ROM products. For details of the operating voltage, refer to "■ ELECTRICAL CHARACTERISTICS".

• Difference MOD Pins

A pull-down resistor is provided for the MOD pin of the MASK ROM product.

■ PIN ASSIGNMENT





■ PIN DESCRIPTION

Pin no.			I/O		
SSOP*1	SOP*2	Pin name	circuit type*3	Function	
1	1	P16	Н	General-purpose I/O port	
2	2	PF0	V	Canaral numbers I/O part for large surrent	
3	3	PF1	K	General-purpose I/O port for large current	
4	4	MOD	В	Operating mode designation pin	
5	5	X0	۸	Main clock oscillation input pin	
6	6	X1	А	Main clock oscillation input/output pin	
7	7	Vss	_	Power supply pin (GND)	
8	8	Vcc	_	Power supply pin	
9	9	С	_	Capacity connection pin	
10	10	PG2/X1A	H/A	Single clock product is general-purpose port (PG2) . Dual clock product is sub clock input/output oscillation pin (32 kHz) .	
11	11	PG1/X0A	11//	Single clock product is general-purpose port (PG1) . Dual clock product is sub clock input oscillation pin (32 kHz) .	
12	12	RST	B'	Reset pin	
13	13	AVcc	_	A/D converter power supply pin	
14	14	AVss	_	A/D converter power supply pin (GND)	
15	15	P00/INT00/ AN00/ PPG00		General-purpose I/O port Shared with external interrupt input (INT00), A/D converter analog input (AN00) and 8/16-bit PPG ch.0 output (PPG00).	
16	16	P01/INT01/ AN01/ PPG01	6	General-purpose I/O port Shared with external interrupt input (INT01), A/D converter analog input (AN01) and 8/16-bit PPG ch.0 output (PPG01).	
17	17	P02/INT02/ AN02/SCK	D	General-purpose I/O port Shared with external interrupt input (INT02), A/D converter analog input (AN02) and LIN-UART clock I/O (SCK).	
18	18	P03/INT03/ AN03/SOT		General-purpose I/O port Shared with external interrupt input (INT03), A/D converter analog input (AN03) and LIN-UART data output (SOT).	
20	19	P04/INT04/ AN04/SIN	E	General-purpose I/O port Shared with external interrupt input (INT04), A/D converter analog input (AN04) and LIN-UART data input (SIN).	
21	20	P05/INT05/ AN05/TO00		General-purpose I/O port Shared with external interrupt input (INT05 & INT06), A/D converte analog input (AN05 & AN06) and 8/16-bit compound timer ch.0 output (TO00 & TO01). General-purpose I/O port Shared with external interrupt input (INT07) and A/D converter analog input (AN07).	
22	21	P06/INT06/ AN06/TO01	D		
23	22	P07/INT07/ AN07			

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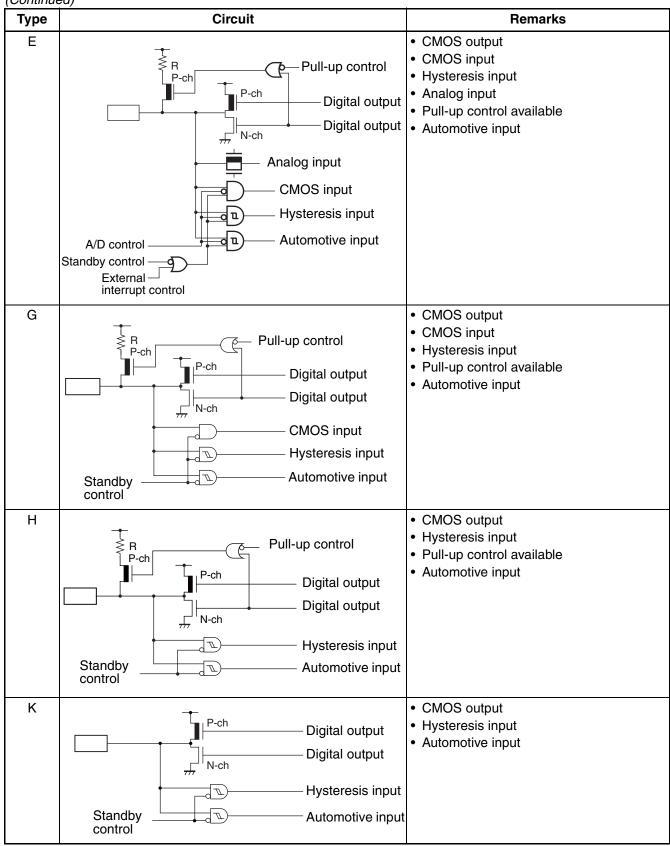
Pin no. I/O					
SSOP*1	SOP*2	Pin name	circuit type*3	Function	
24	23	P10/UIO	G	General-purpose I/O port Shared with UART/SIO ch.0 data input (UI0)	
25	24	P11/UO0		General-purpose I/O port Shared with UART/SIO ch.0 data output (UO0)	
27	25	P12/UCK0/ EC0		General-purpose I/O port Shared with UART/SIO ch.0 clock I/O (UCK0) and 8/16-bit compound timer ch.0 clock input (EC0)	
28	26	P13/TRG0/ ADTG	Н	General-purpose I/O port Shared with 16-bit PPG ch.0 trigger input (TRG0) and A/D converter trigger input (ADTG)	
29	27	P14/PPG0		General-purpose I/O port Shared with 16-bit PPG ch.0 output (PPG0)	
30	28	P15		General-purpose I/O port	
19,26	_	NC	_	Internally connected pins. Be sure to leave it open.	

*1 : FPT-30P-M02 *2 : FPT-28P-M17

*3 : For the I/O circuit type, refer to "■ I/O CIRCUIT TYPE".

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
А	X1 (X1A) Clock input Standby control	 Oscillation circuit High-speed side Feedback resistance: approx. 1 MΩ Low-speed side Feedback resistance: approx. 10 MΩ
В	R Mode input	Only for input • Hysteresis input • Pull-down resistor available only to MASK ROM product
B'	Reset input N-ch Reset output	Hysteresis input only for MASK ROM product Reset output
D	P-ch Digital output Digital output N-ch Analog input A/D control Standby control External interrupt control	CMOS output Hysteresis input Analog input Pull-up control available Automotive input



■ HANDLING DEVICES

• Preventing latch-up

Care must be taken to ensure that maximum voltage ratings are not exceeded when the devices are used. Latch-up may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input and output pins other than medium- and high-withstand voltage pins or if voltage higher than the rating voltage is applied between Vcc pin and Vss pin.

When latch-up occurs, power supply current increases rapidly and might thermally damage elements. Also, take care to prevent the analog power supply voltage (AVcc) and analog input voltage from exceeding the digital power supply voltage (Vcc) when the analog system power supply is turned on or off.

Stable supply voltage

Supply voltage should be stabilized.

A sudden change in power supply voltage may cause a malfunction even within the guaranteed operating range of the V_{CC} power supply voltage.

For stabilization, in principle, keep the variation in $V_{\rm CC}$ ripple (p-p value) in a commercial frequency range (50 / 60 Hz) not to exceed 10% of the standard $V_{\rm CC}$ value and suppress the voltage variation so that the transient variation rate does not exceed 0.1 V/ms during a momentary change such as when the power supply is switched.

Precautions for use of external clock

Even when an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from the sub clock mode or stop mode.

PIN CONNECTION

• Treatment of unused pins

Leaving unused input pins unconnected can cause abnormal operation or latch-up, leading to permanent damage. Unused input pins should always be pulled up or down through resistance of at least $2 \text{ k}\Omega$. Any unused input/output pins may be set to the output mode and left open, or set to the input mode and treated the same as unused input pins. If there is any unused output pin, make it open.

• Treatment of power supply pins on A/D converter

Connect to be AVcc = Vcc and AVss = Vss even if the A/D converter is not in use.

Noise riding on the AV $_{\text{CC}}$ pin may cause accuracy degradation. So, connect approx. 0.1 μ F ceramic capacitor as a bypass capacitor between AV $_{\text{CC}}$ and AV $_{\text{SS}}$ pins in the vicinity of this device.

• Power Supply Pins

In products with multiple V_{CC} or V_{SS} pins, the pins of the same potential are internally connected in the device to avoid abnormal operations including latch-up. However, all the pins must be connected to external power supply and a ground line to lower the electro-magnetic emission level, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating. Moreover, connect the current supply source with the V_{CC} and V_{SS} pins of this device at the low impedance.

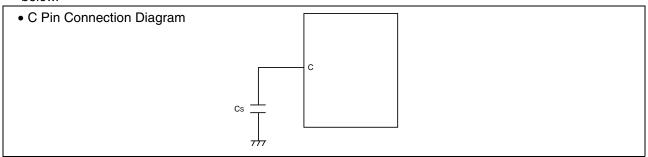
It is also advisable to connect a ceramic bypass capacitor of approximately 0.1 μ F between V_{CC} and V_{SS} pins near this device.

• Mode pin (MOD)

Connect the mode pin directly to Vcc or Vss pins.

To prevent the device unintentionally entering the test mode due to noise, lay out the printed circuit board so as to minimize the distance from the mode pins to Vcc or Vss pins and to provide a low-impedance connection.

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of V_{CC} pin must have a capacitance value higher than C_{S} . For connection of smoothing capacitor C_{S} , refer to the diagram below.



• Analog power supply

Always set the same potential to AVcc $\,$ pin and Vcc $\,$ pin. When Vcc $\,$ AVcc, the current may flow through the AN00 to AN07 pins.

• NC pins

Any pins marked "NC" (not connected) must be left open.

■ PROGRAMMING FLASH MEMORY MICROCONTROLLERS USING PARALLEL PROGRAMMER

• Supported parallel programmers and adapters

The following table lists supported parallel programmers and adapters.

Package	Applicable adapter model	Parallel programmers
FPT-28P-M17	TEF110-95F136HSPF	AF9708 (Since Rev 02.43E)
FPT-30P-M02	TEF110-95F136MB	AF9709/B (Since Rev 02.43E)

Note: : For information about applicable adapter models and parallel programmers, contact the following: Flash Support Group, Inc. TEL: +81-53-428-8380

Sector configuration

The following table shows sector-specific addresses for data access by CPU and by the parallel programmer.

MB95F136MBS/F136NBS/F136MBW/F136NBW/F136JBS/F136JBW	(32 I	≺bytes)

Flash memory	CPU address	Programmer address*
32 Kbytes		18000 _H
,	FFFF _H	1FFFF _H

^{*:} Programmer addresses are corresponding to CPU addresses, used when the parallel programmer programs data into Flash memory.

These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

• Programming method

- 1) Set the type code of the parallel programmer to "17237".
- 2) Load program data to programmer addresses 18000_H to 1FFFF_H.
- 3) Write data with the parallel programmer.

• MB95F134MBS/F134NBS/F134JBS/F134MBW/F134NBW/F134JBW (16 Kbytes)

Flash memory	CPU address	Programmer address*
16 Kbytes	С000н	1C000H
	FFFF _H	1FFFF _H

^{*:} Programmer addresses are corresponding to CPU addresses, used when the parallel programmer programs data into Flash memory.

Programming method

- 1) Set the type code of the parallel programmer to "17237".
- 2) Load program data to programmer addresses 1C000_H to 1FFFF_H.
- 3) Write data with the parallel programmer.

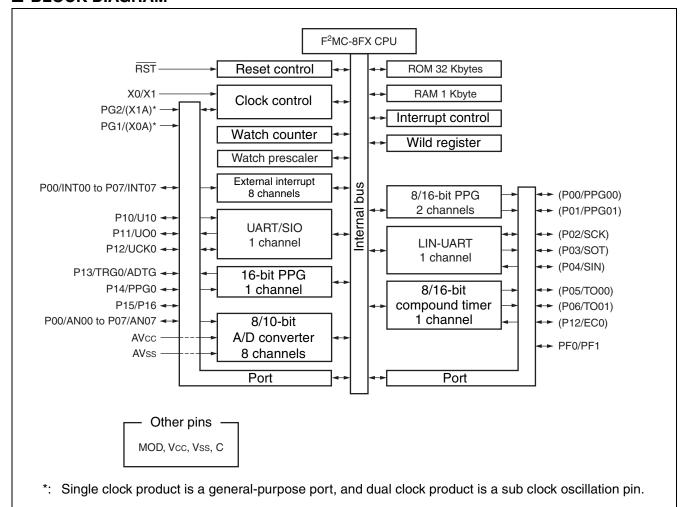
These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

MB95F133MBS/F133NBS/F133JBS/F133MBW/F133NBW/F133JBW (8 Kbytes)								
Flash memory	CPU address	Programmer address*						
8 Kbytes	Е000н	1 <u>E</u> 000 _H						
	FFFF _H	<u>1FFFF</u>						
*: Programmer addresses are corresponding to CPU addresses, used when the parallel programmer programs data into Flash memory. These programmer addresses are used for the parallel programmer to program or erase data in								
Flash memory.								

• Programming method

- 1) Set the type code of the parallel programmer to "17237".
- 2) Load program data to programmer addresses 1E000 H to 1FFFFH.
- 3) Write data with the parallel programmer.

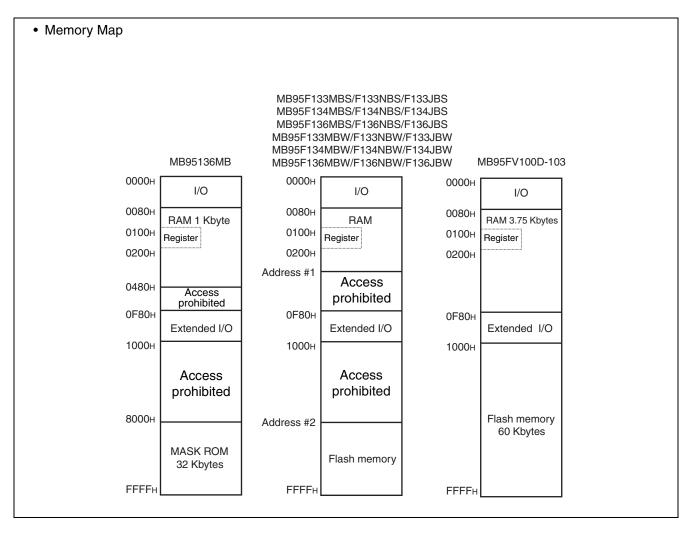
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

Memory space of the MB95130MB series is 64 Kbytes and consists of I/O area, data area, and program area. The memory space includes special-purpose areas such as the general-purpose registers and vector table. Memory map of the MB95130MB series is shown below.



	Flash memory	RAM	Address #1	Address #2
MB95F133MBS/F133NBS/F133JBS	8 Kbytes	256 bytes	0180н	Е000н
MB95F133MBW/F133NBW/F133JBW	o Ruyles	230 bytes	ОТООН	СОООН
MB95F134MBS/F134NBS/F134JBS	16 Khytoo	512 bytes	0280н	С000н
MB95F134MBW/F134NBW/F134JBW	16 Kbytes	512 bytes	U20UH	Сооон
MB95F136MBS/F136NBS/F136JBS	32 Kbytes	1 Kbyte	0480н	8000⊦
MB95F136MBW/F136NBW/F136JBW	32 Noyles	i Kbyte	0460H	8000н

2. Register

The MB95130MB series has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The dedicated registers are as include:

Program counter (PC) : A 16-bit register to indicate locations where instructions are stored.

Accumulator (A) : A 16-bit register for temporary storage of arithmetic operations. In the case of

an 8-bit data processing instruction, the lower 1-byte is used.

Temporary accumulator (T) : A 16-bit register which performs arithmetic operations with the accumulator.

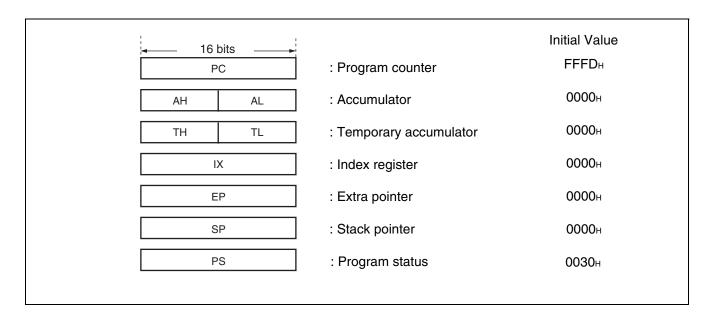
In the case of an 8-bit data processing instruction, the lower 1-byte is used.

Index register (IX) : A 16-bit register for index modification

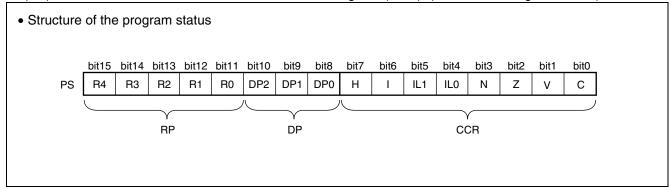
Extra pointer (EP) : A 16-bit pointer to point to a memory address. Stack pointer (SP) : A 16-bit register to indicate a stack area.

Program status (PS) : A 16-bit register for storing a register bank pointer, a direct bank pointer, and

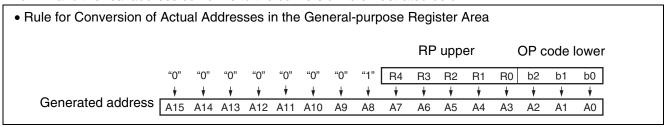
a condition code register



The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and a direct bank pointer (DP) and the lower 8 bits for use as a condition code register (CCR). (Refer to the diagram below.)



The RP indicates the address of the register bank currently being used. The relationship between the content of RP and the real address conforms to the conversion rule illustrated below:



The DP specifies the area for mapping instructions (16 different types of instructions such as MOV A and dir) using direct addresses to 0080_H to 00FF_H.

Direct bank pointer (DP2 to DP0)	Specified address area	Mapping area		
XXX _B (no effect to mapping)	0000н to 007Fн	0000н to 007Fн (without mapping)		
000₅ (initial value)		0080н to 00FFн (without mapping)		
001в		0100н to 017Fн		
010в		0180н to 01FFн		
011в	0080н to 00FFн	0200н to 027Fн		
100в	OUGOH TO OOLLEH	0280н to 02FFн		
101в		0300н to 037Fн		
110в		0380н to 03FFн		
111в		0400н to 047Fн		

The CCR consists of the bits indicating arithmetic operation results or transfer data content and the bits that control CPU operations at interrupt.

H flag : Set to "1" when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared to "0" otherwise. This flag is for decimal adjustment instructions.

I flag : Interrupt is enabled when this flag is set to "1". Interrupt is disabled when this flag is set to "0". The flag is cleared to "0" when reset.

IL1, IL0 : Indicates the level of the interrupt currently enabled. Processes an interrupt only if its request level is higher than the value indicated by these bits.

IL1	IL0	Interrupt level	Priority
0	0	0	High
0	1	1	↑
1	0	2	<u> </u>
1	1	3	Low (no interruption)

N flag : Set to "1" if the MSB is set to "1" as the result of an arithmetic operation. Cleared to "0" when the

Z flag : Set to "1" when an arithmetic operation results in "0". Cleared to "0" otherwise.

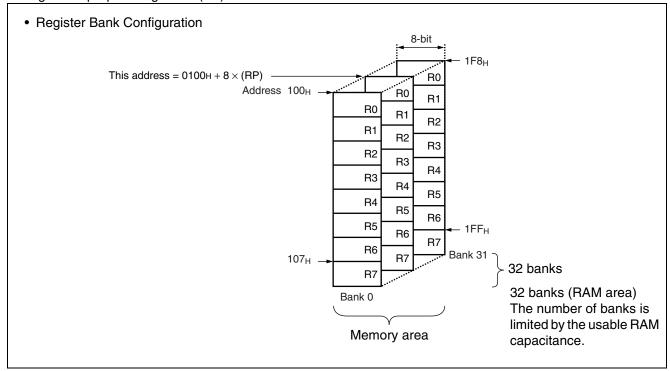
V flag : Set to "1" if the complement on 2 overflows as a result of an arithmetic operation. Cleared to "0" otherwise

C flag : Set to "1" when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared to "0" otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: 8-bit data storage registers

The general-purpose registers are 8 bits and located in the register banks on the memory. 1-bank contains 8 registers. Up to a total of 32 banks can be used on the MB95130MB series. The bank currently in use is specified by the register bank pointer (RP), and the lower 3 bits of OP code indicates the general-purpose register 0 (R0) to general-purpose register 7 (R7).



■ I/O MAP

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000В
0001н	DDR0	Port 0 direction register	R/W	0000000В
0002н	PDR1	Port 1 data register	R/W	0000000В
0003н	DDR1	Port 1 direction register	R/W	0000000В
0004н		(Disabled)		_
0005н	WATR	Oscillation stabilization wait time setting register	R/W	111111111
0006н	PLLC	PLL control register	R/W	0000000В
0007н	SYCC	System clock control register	R/W	1010Х011в
0008н	STBC	Standby control register	R/W	0000000В
0009н	RSRR	Reset source register	R/W	XXXXXXXXB
000Ан	TBTC	Timebase timer control register	R/W	0000000В
000Вн	WPCR	Watch prescaler control register	R/W	0000000В
000Сн	WDTC	Watchdog timer control register	R/W	0000000В
000Dн to 0027н	_	(Disabled)		_
0028н	PDRF	Port F data register		0000000В
0029н	DDRF	Port F direction register	R/W	0000000В
002Ан	PDRG	Port G data register	R/W	0000000В
002Вн	DDRG	Port G direction register	R/W	0000000В
002Сн	PUL0	Port 0 pull-up register	R/W	0000000В
002Dн	PUL1	Port 1 pull-up register	R/W	0000000В
002Ен to 0034н	_	(Disabled)		_
0035н	PULG	Port G pull-up register	R/W	0000000В
0036н	T01CR1	8/16-bit compound timer 01 control status register 1 ch.0	R/W	0000000В
0037н	T00CR1	8/16-bit compound timer 00 control status register 1 ch.0	R/W	0000000в
0038н, 0039н	_	(Disabled)	_	_
003Ан	PC01	8/16-bit PPG1 control register ch.0	R/W	0000000В
003Вн	PC00	8/16-bit PPG0 control register ch.0	R/W	0000000В
003Сн to 0041н	_	(Disabled)	_	_
0042н	PCNTH0	16-bit PPG control status register (Upper byte) ch.0	R/W	0000000в
0043н	PCNTL0	16-bit PPG control status register (Lower byte) ch.0	R/W	0000000В

Address	Register abbreviation	Register name	R/W	Initial value
0044н to 0047н	_	(Disabled)		_
0048н	EIC00	External interrupt circuit control register ch.0,ch.1	R/W	00000000В
0049н	EIC10	External interrupt circuit control register ch.2,ch.3	R/W	0000000
004Ан	EIC20	External interrupt circuit control register ch.4,ch.5	R/W	0000000В
004Вн	EIC30	External interrupt circuit control register ch.6,ch.7	R/W	0000000В
004Сн to 004Fн	_	(Disabled)	_	_
0050н	SCR	LIN-UART serial control register	R/W	0000000В
0051н	SMR	LIN-UART serial mode register	R/W	0000000В
0052н	SSR	LIN-UART serial status register	R/W	00001000в
0053н	RDR/TDR	LIN-UART reception/transmission data register	R/W	0000000В
0054н	ESCR	LIN-UART extended status control register	R/W	00000100в
0055н	ECCR	LIN-UART extended communication control register		000000XXB
0056н	SMC10	UART/SIO serial mode control register 1 ch.0	R/W	0000000В
0057н	SMC20	UART/SIO serial mode control register 2 ch.0	R/W	00100000в
0058н	SSR0	UART/SIO serial status register ch.0	R/W	0000001в
0059н	TDR0	UART/SIO serial output data register ch.0	R/W	0000000В
005Ан	RDR0	UART/SIO serial input data register ch.0	R	0000000В
005Вн to 006Вн	_	(Disabled)	_	_
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000В
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000В
006Ен	ADDH	8/10-bit A/D converter data register (Upper byte)	R/W	0000000В
006Fн	ADDL	8/10-bit A/D converter data register (Lower byte)	R/W	0000000В
0070н	WCSR	Watch counter status register	R/W	0000000В
0071н	_	(Disabled)	_	_
0072н	FSR	Flash memory status register	R/W	000Х0000в
0073н	_	(Disabled)	_	_
0074н	_	(Disabled)	_	_
0075н		(Disabled)		_
0076н	WREN	Wild register address compare enable register	R/W	0000000В
0077н	WROR	Wild register data test setting register	R/W	0000000В

(Continued)

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Address	Register abbreviation	Register name	R/W	Initial value
0078н	_	(Register bank pointer (RP) Mirror of direct bank pointer (DP)	_	_
0079н	ILR0	Interrupt level setting register 0	R/W	111111111
007Ан	ILR1	Interrupt level setting register 1	R/W	111111111
007Вн	ILR2	Interrupt level setting register 2	R/W	111111111
007Сн	ILR3	Interrupt level setting register 3	R/W	111111111
007Dн	ILR4	Interrupt level setting register 4	R/W	111111111
007Ен	ILR5	Interrupt level setting register 5	R/W	111111111
007Fн	_	(Disabled)		_
0F80н	WRARH0	Wild register address setting register (Upper byte) ch.0	R/W	0000000В
0F81н	WRARL0	Wild register address setting register (Lower byte) ch.0	R/W	0000000В
0F82н	WRDR0	Wild register data setting register ch.0	R/W	0000000В
0F83н	WRARH1	Wild register address setting register (Upper byte) ch.1	R/W	0000000В
0F84н	WRARL1	Wild register address setting register (Lower byte) ch.1	R/W	0000000В
0F85н	WRDR1	Wild register data setting register ch.1	R/W	0000000В
0F86н	WRARH2	Wild register address setting register (Upper byte) ch.2		0000000В
0F87н	WRARL2	Wild register address setting register (Lower byte) ch.2	R/W	0000000В
0F88н	WRDR2	Wild register data setting register ch.2	R/W	0000000В
0F89н to 0F91н	_	(Disabled)	_	_
0F92н	T01CR0	8/16-bit compound timer 01 control status register 0 ch.0	R/W	0000000В
0F93н	T00CR0	8/16-bit compound timer 00 control status register 0 ch.0	R/W	0000000В
0F94н	T01DR	8/16-bit compound timer 01 data register ch.0	R/W	0000000В
0F95⊦	T00DR	8/16-bit compound timer 00 data register ch.0	R/W	0000000В
0F96н	TMCR0	8/16-bit compound timer 00/01 timer mode control register ch.0	R/W	00000000в
0F97н to 0F9Вн	_	(Disabled)		_
0F9Сн	PPS01	8/16-bit PPG1 cycle setting buffer register ch.0	R/W	111111111
0F9Dн	PPS00	8/16-bit PPG0 cycle setting buffer register ch.0	R/W	111111111
0F9Eн	PDS01	8/16-bit PPG1 duty setting buffer register ch.0	R/W	111111111
0F9Fн	PDS00	8/16-bit PPG0 duty setting buffer register ch.0	R/W	11111111в
0FA0н to 0FA3н	_	(Disabled)	_	_

(Continued)				1
Address	Register abbreviation	Register name	R/W	Initial value
0FA4н	PPGS	8/16-bit PPG start register	R/W	0000000В
0FA5н	REVC	8/16-bit PPG output inversion register	R/W	0000000В
0FA6н to 0FA9н		(Disabled)	_	
0ГААн	PDCRH0	16-bit PPG down counter register (Upper byte) ch.0	R	0000000В
0FАВн	PDCRL0	16-bit PPG down counter register (Lower byte) ch.0	R	0000000в
0FACн	PCSRH0	16-bit PPG cycle setting buffer register (Upper byte) ch.0	R/W	11111111В
0FADн	PCSRL0	16-bit PPG cycle setting buffer register (Lower byte) ch.0	R/W	111111111
0FAEн	PDUTH0	16-bit PPG duty setting buffer register (Upper byte) ch.0	R/W	111111111
0FAFн	PDUTL0	16-bit PPG duty setting buffer register (Lower byte) ch.0	R/W	111111111
0FB0н to 0FBBн	_	(Disabled)	_	_
0FBCн	BGR1	LIN-UART baud rate generator register 1	R/W	0000000в
0FBDн	BGR0	LIN-UART baud rate generator register 0	R/W	0000000В
0FBEн	PSSR0	UART/SIO dedicated baud rate generator prescaler selection register ch.0		0000000В
0FBFн	BRSR0	UART/SIO dedicated baud rate generator baud rate setting register ch.0		0000000в
0FC0н to 0FC2н	_	(Disabled)		_
0FС3 _н	AIDRL	A/D input disable register (Lower byte)	R/W	0000000В
0FC4н to 0FE2н	_	(Disabled)	_	_
0FE3н	WCDR	Watch counter data register	R/W	00111111в
0FE4н to 0FE6н	_	(Disabled)	_	_
0FE7н	ILSR2	Input level select register 2 (option)	R/W	0000000В
0FE8н, 0FE9н	_	(Disabled)	_	_
0FEAн	CSVCR	Clock supervisor control register	R/W	00011100в
0FEBн to 0FEDн	_	(Disabled)	_	_
0FEE _H	ILSR	Input level select register	R/W	0000000В
0FEF _H	WICR	Interrupt pin control register	R/W	01000000в
0FF0н to 0FFFн	_	(Disabled)		_

• R/W access symbols

R/W : Readable / Writable

R : Read only W : Write only

• Initial value symbols

0 : The initial value of this bit is "0".1 : The initial value of this bit is "1".

X : The initial value of this bit is undefined.

Note: : Do not write to the " (Disabled) ". Reading the " (Disabled) " returns an undefined value.

■ INTERRUPT SOURCE TABLE

	Interrupt	Vector tab	le address	Bit name of	Same level
Interrupt source	request number	Upper	Lower	interrupt level setting register	priority order (at simultaneous occurrence)
External interrupt ch.0	IDOO	FFFA⊦	FFFB _H	1.00 [1 . 0]	High
External interrupt ch.4	IRQ0	FFFAH	ГГГОН	L00 [1 : 0]	A
External interrupt ch.1	IDO4	FFF0	FFF0	1 04 54 01	†
External interrupt ch.5	IRQ1	FFF8 _H	FFF9⊦	L01 [1 : 0]	
External interrupt ch.2	IDOO	FFFC		1.00.14 . 01	
External interrupt ch.6	IRQ2	FFF6 _H	FFF7 _H	L02 [1 : 0]	
External interrupt ch.3	IDOs	FFF4		1.00.14 . 01	
External interrupt ch.7	IRQ3	FFF4 _H	FFF5 _H	L03 [1 : 0]	
UART/SIO ch.0	IRQ4	FFF2 _H	FFF3 _H	L04 [1 : 0]	
8/16-bit compound timer ch.0 (Lower)	IRQ5	FFF0 _H	FFF1 _H	L05 [1:0]	
8/16-bit compound timer ch.0 (Higher)	IRQ6	FFEEH	FFEFH	L06 [1:0]	
LIN-UART (reception)	IRQ7	FFECH	FFEDH	L07 [1:0]	
LIN-UART (transmission)	IRQ8	FFEA⊦	FFEB _H	L08 [1 : 0]	
(Unused)	IRQ9	FFE8 _H	FFE9н	L09 [1 : 0]	
(Unused)	IRQ10	FFE6⊦	FFE7 _H	L10 [1 : 0]	
(Unused)	IRQ11	FFE4 _H	FFE5 _H	L11 [1:0]	
8/16-bit PPG ch.0 (Upper)	IRQ12	FFE2 _H	FFE3 _H	L12 [1 : 0]	
8/16-bit PPG ch.0 (Lower)	IRQ13	FFE0 _H	FFE1 _H	L13 [1 : 0]	
(Unused)	IRQ14	FFDEH	FFDF⊦	L14 [1 : 0]	
16-bit PPG ch.0	IRQ15	FFDCH	FFDD _H	L15 [1 : 0]	
(Unused)	IRQ16	FFDАн	FFDB⊦	L16 [1 : 0]	
(Unused)	IRQ17	FFD8 _H	FFD9 _H	L17 [1 : 0]	
8/10-bit A/D converter	IRQ18	FFD6н	FFD7 _H	L18 [1 : 0]	
Timebase timer	IRQ19	FFD4 _H	FFD5 _H	L19 [1 : 0]	
Watch prescaler/Watch counter	IRQ20	FFD2 _H	FFD3 _H	L20 [1 : 0]	
(Unused)	IRQ21	FFD0 _H	FFD1 _H	L21 [1 : 0]	
(Unused)	IRQ22	FFCEH	FFCF _H	L22 [1 : 0]	▼
Flash memory	IRQ23	FFCCH	FFCDH	L23 [1 : 0]	Low

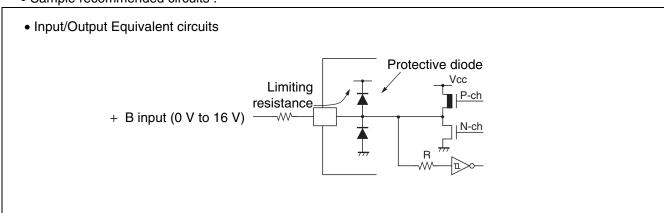
■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

Davamatav	Cumbal	Rating		l lm!4	Damaika	
Parameter	Symbol	Min	Max	Unit	Remarks	
Power supply voltage*1	Vcc AVcc	Vss - 0.3	Vss + 6.0	V	*2	
Input voltage*1	Vı	Vss - 0.3	Vss + 6.0	V	*3	
Output voltage*1	Vo	Vss - 0.3	Vss + 6.0	V	*3	
Maximum clamp current	I CLAMP	- 2.0	+ 2.0	mA	Applicable to pins*4	
Total maximum clamp current	Σ CLAMP	_	20	mA	Applicable to pins*4	
"L" level maximum	lo _{L1}		15	mA	Other than PF0, PF1	
output current	lol2		15	IIIA	PF0, PF1	
"L" level average	lolav1		4	mA	Other than PF0, PF1 Average output current = operating current × operating ratio (1 pin)	
current	lolav2		12	1117.	PF0, PF1 Average output current = operating current × operating ratio (1 pin)	
"L" level total maximum output current	Σ lol	_	100	mA		
"L" level total average output current	Σ lolav	_	50	mA	Total average output current = operating current × operating ratio (Total of pins)	
"H" level maximum	І он1		– 15	mΛ	Other than PF0, PF1	
output current	І он2	_	– 15	mA	PF0, PF1	
"H" level average	Iohav1			- 4	- mA	Other than PF0, PF1 Average output current = operating current × operating ratio (1 pin)
current	Iонаv2		- 8	IIIA	PF0, PF1 Average output current = operating current × operating ratio (1 pin)	
"H" level total maximum output current	Σ Іон	_	- 100	mA		
"H" level total average output current	ΣΙοнαν	_	- 50	mA	Total average output current = operating current × operating ratio (Total number of pins)	
Power consumption	Pd	_	320	mW		
Operating temperature	TA	- 40	+ 105	°C		
Storage temperature	Tstg	– 55	+ 150	°C		

(Continued)

- *1: These parameters are based on the condition that both AVss and Vss are 0.0 V.
- *2: Apply equal potential to AVcc and Vcc.
- *3: V_I and V_O should not exceed Vcc + 0.3 V. V_I must not exceed the rating voltage. However, if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.
- *4: Applicable pins: P10 to P15, PF0, PF1 (Inapplicable pins: PG1, PG2)
 - Use within recommended operating conditions.
 - Use at DC voltage (current).
 - +B signal is an input signal that exceeds Vcc voltage. The + B signal should always be applied a limiting resistance placed between the + B signal and the microcontroller.
 - The value of the limiting resistance should be set so that when the + B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
 - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the Vcc pin, and this affects other devices.
 - Note that if the + B signal is inputted when the microcontroller power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
 - Note that if the + B input is applied during power-on, the power supply is provided from the pins and the resulting power supply voltage may not be sufficient to operate the power-on reset.
 - Care must be taken not to leave the + B input pin open.
 - •Note that analog system input/output pins other than the A/D input pins (LCD drive pins, etc.) cannot accept +B signal input.
 - Sample recommended circuits :



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

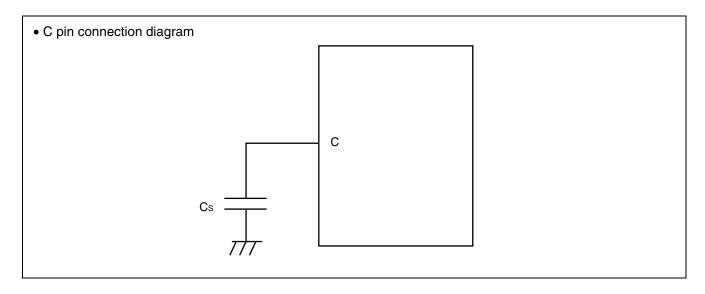
2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks	
Farameter	Зупівої	Min			nemarks	
Power supply voltage	Vcc,	2.42*2	5.5* ¹	V	At normal operation	
Fower supply voltage	AVcc	2.3	5.5	V	Holds condition in stop mode	
Smoothing capacitor	Cs	0.1	1.0	μF	*3	
Operating temperature	TA	- 40	+ 105	°C		

^{*1:} The value varies depending on the operating frequency.

^{*3:} Use ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of Vcc pin must have a capacitance value higher than Cs. For connection of smoothing capacitor Cs, refer to the diagram below.



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

^{*2:} The value is 2.88 V when the low-voltage detection reset is used.

3. DC Characteristics

(Vcc = = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, Ta = - 40 °C to + 105 °C)

Dawamatan	Or made at	Pin name	0		Value	•	11	Remarks	
Parameter	Symbol		Condition	Min	Тур	Max	Unit		
	Vihi	P04 (selectable in SIN), P10 (selectable in UI0)	_	0.7 Vcc		Vcc + 0.3	V	Hysteresis input	
"H" level	Vihsi	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	0.8 Vcc		Vcc + 0.3	V	Hysteresis input	
input voltage	VIHA	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	0.8 Vcc		Vcc + 0.3	V	Pin input at selecting of Automotive input level	
	Vana	RST, MOD	_	0.7 Vcc		Vcc + 0.3	V	CMOS input (Flash memory product)	
	V _{ІНМ}	Not, MOD	_	0.8 Vcc	_	Vcc + 0.3	V	Hysteresis input (MASK ROM product)	
	VIL	P04 (selectable in SIN), P10 (selectable in UI0)	_	Vss - 0.3		0.3 Vcc	V	Hysteresis input	
"I" lovel	VILS	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	Vss - 0.3		0.2 Vcc	V	Hysteresis input	
"L" level input voltage	VILA	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	_	Vss - 0.3		0.5 Vcc	V	Pin input at selecting of Automotive input level	
	VILM	m RST, MOD	_	Vss - 0.3	_	0.3 Vcc	V	CMOS input (Flash memory product)	
			_	Vss - 0.3	_	0.2 Vcc	V	Hysteresis input (MASK ROM product)	
"H" level output	Vон1	Output pins other than PF0, PF1	$I_{OH} = -4.0 \text{ mA}$	Vcc - 0.5	_	_	٧		
voltage	V _{OH2}	PF0, PF1	Iон = $-8.0 mA$	Vcc - 0.5		_	V		
"L" level output voltage	V _{OL1}	Output pins other than PF0 to PF7, RST*1	IoL = 4.0 mA	_	_	0.4	V		
Tollago	V _{OL2}	PF0, PF1	IoL = 12 mA			0.4	V		

 $(Vcc = AVcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, TA = -40 °C to +105 °C)$

	Symbol	Pin name		Value			Het	
Parameter			Condition	Min	Тур	Max	Unit	Remarks
Input leakage current (Hi-Z out- put leakage current)	lu	P00 to P07, P10 to P16, PF0, PF1, PG1, PG2	0.0 V < V _I < V _{CC}	– 5	_	+ 5	μΑ	When the pull-up prohibition setting
Pull-up resistor	Rpull	P00 to P07, P10 to P16, PG1, PG2	V1 = 0.0 V	25	50	100	kΩ	When the pull-up permission setting
Pull-down resistor	Rмор	MOD	$V_{I} = V_{CC}$	50	100	200	kΩ	MASK ROM product only
Input capacity	Cin	Other than AVcc, AVss, C, Vcc and Vss	f = 1 MHz	_	5	15	pF	
	lcc	Vcc (External clock operation)	Vcc = 5.5 V FcH = 20 MHz FMP = 10 MHz Main clock mode (divided by 2)	_	9.5	12.5	mA	Flash memory product (at other than Flash memory writing and erasing)
					30	35	mA	Flash memory product (at Flash memory writing and erasing)
Power					7.2	9.5	mA	MASK ROM product
supply current* ²			F _{CH} = 32 MHz F _{MP} = 16 MHz Main clock mode (divided by 2)		15.2	20.0	mA	Flash memory product (at other than Flash memory writing and erasing)
				_	35.7	42.5	mA	Flash memory product (at Flash memory writing and erasing)
				_	11.6	15.2	mA	MASK ROM product

 $(Vcc = AVcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 °C to +105 °C)$

Parameter	Symbol	Pin name	$Vcc = AVcc = 5.0 V \pm 1$	070,7103	Value	0.0 V, 1A	Unit	,
			Condition	Min	Тур	Max		
Power supply current*2	Iccs	Vcc (External clock operation)	Vcc = 5.5 V FcH = 20 MHz FMP = 10 MHz Main Sleep mode (divided by 2)	_	4.5	7.5	mA	
			F _{CH} = 32 MHz F _{MP} = 16 MHz Main Sleep mode (divided by 2)	—	7.2	12.0	mA	
	IccL		$V_{CC} = 5.5 \text{ V}$ $F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 16 \text{ kHz}$ Sub clock mode (divided by 2), $T_A = +25 \text{ °C}$	_	45	100	μА	Dual clock product only
	Iccls		$V_{CC} = 5.5 \text{ V}$ $F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 16 \text{ kHz}$ Sub sleep mode (divided by 2), $T_{A} = +25 ^{\circ}\text{C}$	_	10	81	μА	Dual clock product only
	Ісст		Vcc = 5.5 V FcL = 32 kHz Watch mode Main stop mode TA = +25 °C		4.6	27	μΑ	Dual clock product only
	ICCMPLL		Vcc = 5.5 V FcH = 4 MHz FMP = 10 MHz Main PLL mode (multiplied by 2.5)		9.3	12.5	mA	Flash memory product
				l	7	9.5	mA	MASK ROM product
			F _{CH} = 6.4 MHz F _{MP} = 16 MHz Main PLL mode (multiplied by 2.5)	_	14.9	20.0	mA	Flash memory product
				_	11.2	15.2	mA	MASK ROM product
	Iccspll		$V_{CC} = 5.5 \text{ V}$ $F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 128 \text{ kHz}$ Sub PLL mode (multiplied by 4), $T_A = +25 \text{ °C}$	_	160	400	μА	Dual clock product only

(Continued)

 $(Vcc = AVcc = 5.0 \text{ V} \pm 10\%, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ Ta} = -40 ^{\circ}\text{C to } + 105 ^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
			Condition	Min	Тур	Max	Oilit	
Power supply current*2	Істѕ	Vcc (External clock operation)	$V_{CC} = 5.5 \text{ V}$ $F_{CH} = 10 \text{ MHz}$ Timebase timer mode $T_A = +25 \text{ °C}$		0.15	1.1	mA	
	Іссн	operation)	$V_{CC} = 5.5 \text{ V}$ Sub stop mode $T_A = +25 \text{ °C}$	_	3.5	20.0	μΑ	Main stop mode for single clock product
	la		Vcc = 5.5 V FcH = 16 MHz When A/D conver- sion is in operation	_	2.4	4.7	mA	
	Іан	AVcc	Vcc = 5.5 V FcH = 16 MHz When A/D conversion is stopped TA = + 25 °C	_	1	5	μΑ	

^{*1:} Product without clock supervisor only

- Refer to "4. AC Characteristics: (1) Clock Timing" for Fch and Fcl.
- Refer to "4. AC Characteristics: (2) Source Clock / Machine Clock" for FMP and FMPL.

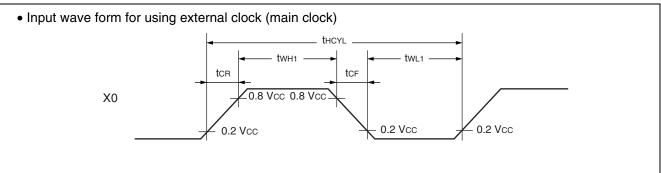
^{*2: •} The power supply current is specified by the external clock. When the low-voltage detection and clock supervisor options are selected, the consumption current values of both the low-voltage detection circuit (ILVD) and the built-in CR oscillator (Icsv) must also be added to the power supply current value.

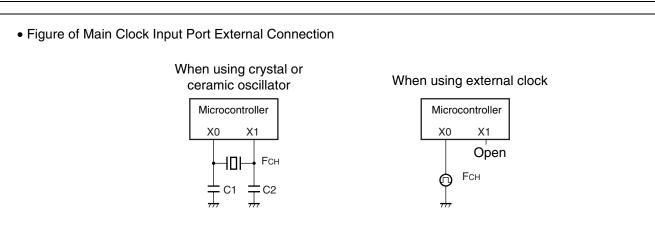
4. AC Characteristics

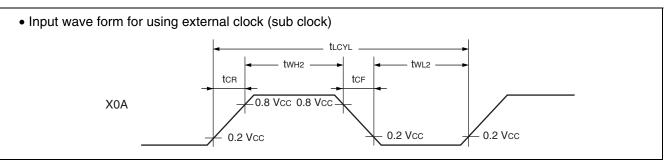
(1) Clock Timing

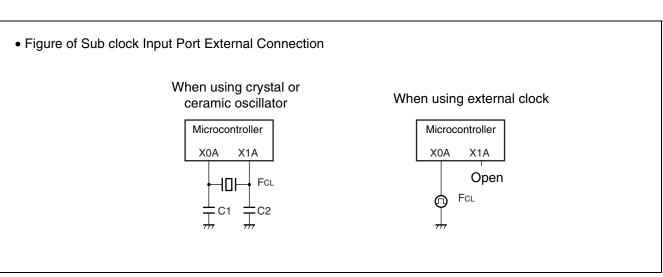
(Vcc = 2.42 V to 5.0 V, AVss = Vss = 0.0 V, $T_A = -40 \, ^{\circ}\text{C}$ to $+105 \, ^{\circ}\text{C}$)

Parameter	Sym-	Pin name	Condi- tion	Value			Heit	Remarks
Parameter	bol			Min	Тур	Max	Unit	nemarks
		X0, X1		1.00	_	16.25	MHz	When using main oscillation circuit
	Fсн			1.00	_	32.50	MHz	When using external clock
				3.00		10.00	MHz	Main PLL multiplied by 1
				3.00	_	8.13	MHz	Main PLL multiplied by 2
Clock frequency				3.00		6.50	MHz	Main PLL multiplied by 2.5
				3.00	_	4.06	MHz	Main PLL multiplied by 4
	FcL	X0A, X1A		_	32.768	_	kHz	When using sub oscillation circuit
				_	32.768	_	kHz	When using sub PLL Vcc = 2.3 V to 3.6 V
	thcyl	X0, X1		61.5	_	1000	ns	When using main oscillation circuit
Clock cycle time				30.8	_	1000	ns	When using external clock
	t LCYL	X0A, X1A		_	30.5	_	μs	When using sub oscillation circuit
Input clock pulse width	twH1	Х0		61.5	_		ns	When using external clock duty ratio is about 30% to
Imput clock puise width	twH2	X0A			15.2		μs	70%.
Input clock rise/fall time	tcr tcr	X0, X0A				5	ns	When using external clock









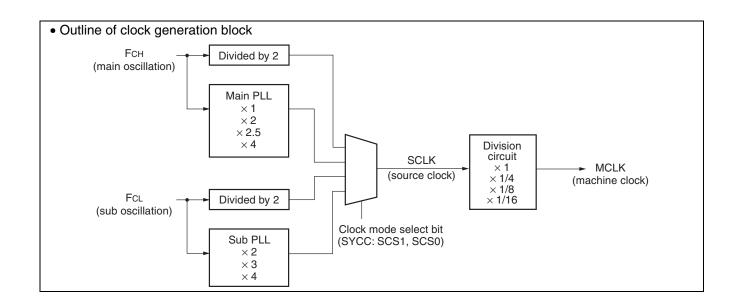
(2) Source Clock / Machine Clock

 $(Vcc = 5.0 \text{ V} \pm 10\%, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C to } + 105 \,^{\circ}\text{C})$

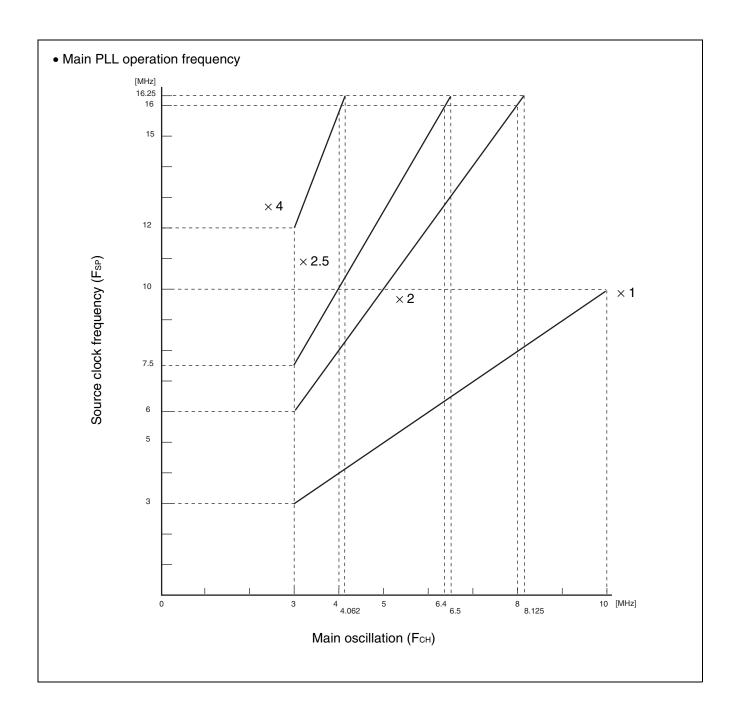
Parameter	Symbol	Pin		Value		Unit	Remarks
Farameter	Syllibol	name	Min	Тур	Max		nemarks
Source clock cycle time*1	tsclk		61.5	l	2000	ns	When using main clock Min: F _{CH} = 8.125 MHz, PLL multiplied by 2 Max: F _{CH} = 1 MHz, divided by 2
(Clock before setting division)	tselk		7.6		61.0	μs	When using sub clock Min: FcL = 32 kHz, PLL multiplied by 4 Max: FcL = 32 kHz, divided by 2
Source clock	Fsp	_	0.50	_	16.25	MHz	When using main clock
frequency	FSPL	_	16.384	_	131.072	kHz	When using sub clock
Machine clock cycle time* ² (Minimum	tmclk		61.5		32000	ns	When using main clock Min: F _{SP} = 16.25 MHz, no division Max: F _{SP} = 0.5 MHz, divided by 16
instruction execution time)	IMOLK	_	7.6		976.5	μs	When using sub clock Min: FSPL = 131 kHz, no division Max: FSPL = 16 kHz, divided by 16
Machine clock	F _{MP}		0.031	_	16.250	MHz	When using main clock
frequency	FMPL		1.024	_	131.072	kHz	When using sub clock

^{*1:} Clock before setting division due to machine clock division ratio selection bit (SYCC: DIV1 and DIV0). This source clock is divided by the machine clock division ratio selection bit (SYCC: DIV1 and DIV0), and it becomes the machine clock. Further, the source clock can be selected as follows.

- Main clock divided by 2
- PLL multiplication of main clock (select from 1, 2, 2.5, 4 multiplication)
- Sub clock divided by 2
- PLL multiplication of sub clock (select from 2, 3, 4 multiplication)
- *2: Operation clock of the microcontroller. Machine clock can be selected as follows.
 - Source clock (no division)
 - Source clock divided by 4
 - Source clock divided by 8
 - Source clock divided by 16



• Operating voltage - Operating frequency (When $T_A = -40 \,^{\circ}\text{C}$ to $+105 \,^{\circ}\text{C}$) • MB95136MB/F133MBS/F133NBS/F133JBS/F134MBS/F134NBS/F134JBS/F136MBS/F136NBS/F136JBS/ MB95F133MBW/F133NBW/F133JBW/F134MBW/F134NBW/F134JBW/F136MBW/F136NBW/ MB95F136JBW Sub PLL, sub clock mode and Main clock mode and main PLL mode watch mode operation guarantee range operation guarantee range 5.5 5.5 Operating voltage (V) Operating voltage (V) 3.5 2.42 2.42 16.25 MHz 0.5 MHz 3 MHz 10 MHz 16.384 kHz 32 kHz 131.072 kHz PLL operation guarantee range PLL operation guarantee range Main clock operation guarantee range Source clock frequency (Fsp) Source clock frequency (FSPL) Operating voltage - Operating frequency (When T_A = +5 °C to +35 °C) MB95FV100D-103 Sub PLL, sub clock mode and Main clock mode and main PLL mode watch mode operation guarantee range operation guarantee range 5.5 5.5 Operating voltage (V) Operating voltage (V) 3.5 2.7 2.7 0.5 MHz 3 MHz 10 MHz 16.25 MHz 16.384 kHz 131.072 kHz PLL operation guarantee range PLL operation guarantee range Main clock operation guarantee range Source clock frequency (FSP) Source clock frequency (FSPL)



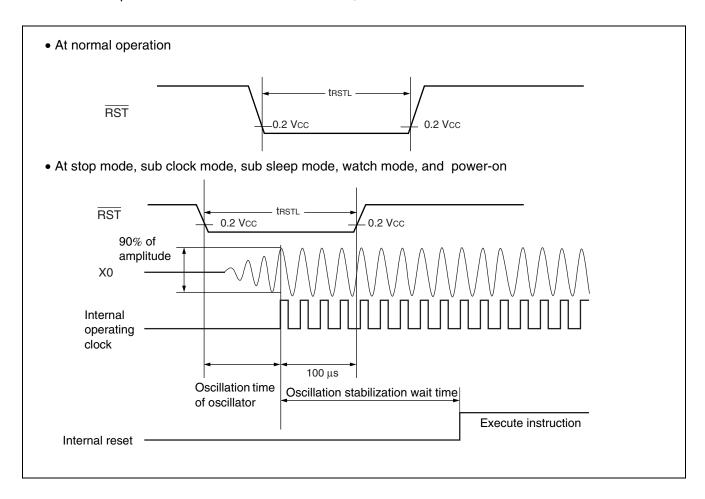
(3) External Reset

 $(Vcc = 5.0 \text{ V} \pm 10\%, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C to } + 105 \,^{\circ}\text{C})$

Parameter	Symbol	Pin	Value			Remarks	
Parameter Symbol		name	Min	Max	Unit	Hemarks	
			2 tмськ*1	_	ns	At normal operation	
RST "L" level pulse width	t RSTL	RST	Oscillation time of oscillator*2 + 100	_	μs	At stop mode, sub clock mode, sub sleep mode & watch mode	
			100		μs	At timebase timer mode	

^{*1 :} Refer to " (2) Source Clock / Machine Clock" for tmclk.

^{*2 :} Oscillation start time of oscillator is the time that the amplitude reaches 90 %. In the crystal oscillator, the oscillation time is between several ms and tens of ms. In ceramic oscillators, the oscillation time is between hundreds of µs and several ms. In the external clock, the oscillation time is 0 ms.

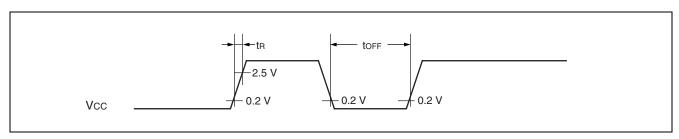


(4) Power-on Reset

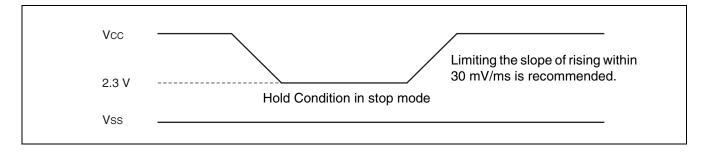
(AVss = Vss = 0.0 V,
$$T_A = -40 \, ^{\circ}\text{C}$$
 to $+105 \, ^{\circ}\text{C}$)

Parameter	Symbol	Pin Condition		Val	lue	Unit	Remarks	
raiailletei	Syllibol	name	Condition	Min	Max	Oilit	nemarks	
Power supply rising time	t⊓		_	_	50	ms		
Power supply cutoff time	toff	Vcc	_	1	_	ms	Waiting time until power-on	

Note: Complete the power-on process within the selected oscillation stabilization wait time.



Note: Sudden change of power supply voltage may activate the power-on reset function. When changing power supply voltages during operation, set the slope of rising within 30 mV/ms as shown below.

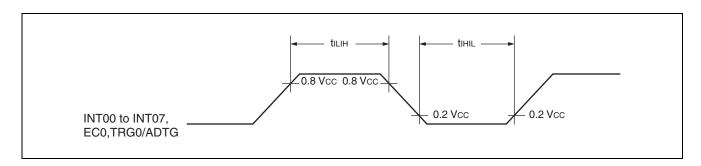


(5) Peripheral Input Timing

(Vcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, Ta = -40 °C to +105 °C)

Parameter	Symbol Pin name		Va	Unit	
raiailletei	Syllibol	riii name	Min	Max	O I III
Peripheral input "H" pulse	tıшн	INT00 to INT07,	2 t mcLk*	_	ns
Peripheral input "L" pulse	tıнıL	EC0, TRG0/ADTG	2 t mcLK*		ns

^{*:} Refer to "(2) Source Clock / Machine Clock" for tmclk.

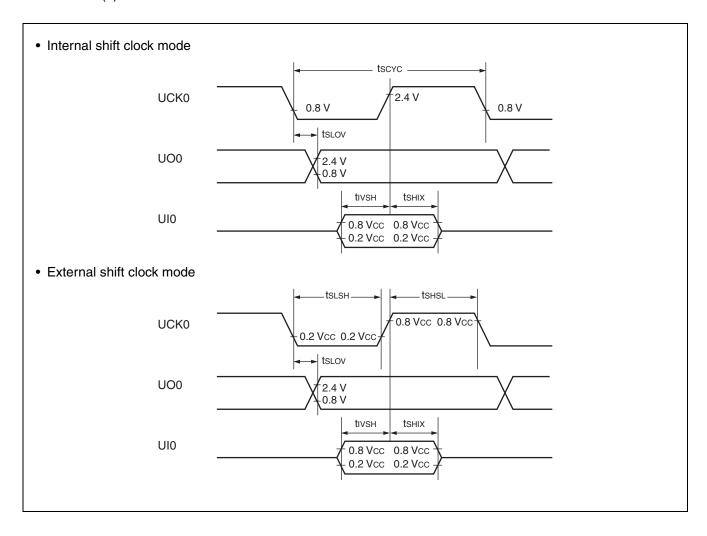


(6) UART/SIO Serial I/O Timing

 $(Vcc = 5.0 \text{ V} \pm 10\%, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_A = -40 \,^{\circ}\text{C to } + 105 \,^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Va	Unit		
Parameter	Syllibol	Pili lialile	Condition	Min	Max		
Serial clock cycle time	tscyc	UCK0		4 t mcLK*	_	ns	
$UCK \downarrow \to UO$ time	tslov	UCK0, UO0	Internal clock	- 190	+190	ns	
Valid UI $→$ UCK $↑$	tıvsн	UCK0, UI0	operation output pin : $C_L = 80 \text{ pF} + 1 \text{ TTL}.$	2 t mclk*	_	ns	
UCK $\uparrow \rightarrow$ valid UI hold time	tsнıx	UCK0, UI0		2 t mcLk*	_	ns	
Serial clock "H" pulse width	t shsl	UCK0		4 t мськ*	_	ns	
Serial clock "L" pulse width	t slsh	UCK0	External clock	4 t mcLK*	_	ns	
$UCK \downarrow \to UO$ time	t sLov	UCK0, UO0	operation output pin :	_	190	ns	
Valid UI → UCK ↑	tıvsн	UCK0, UI0	C _L = 80 pF + 1 TTL.	2 t мськ*	_	ns	
UCK $\uparrow \rightarrow$ valid UI hold time	tsніх	UCK0, UI0		2 t mcLk*	_	ns	

*: Refer to "(2) Source Clock / Machine Clock" for tmclk.



(7) LIN-UART Timing

Sampling at the rising edge of sampling clock*1 and prohibited serial clock delay*2 (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 0)

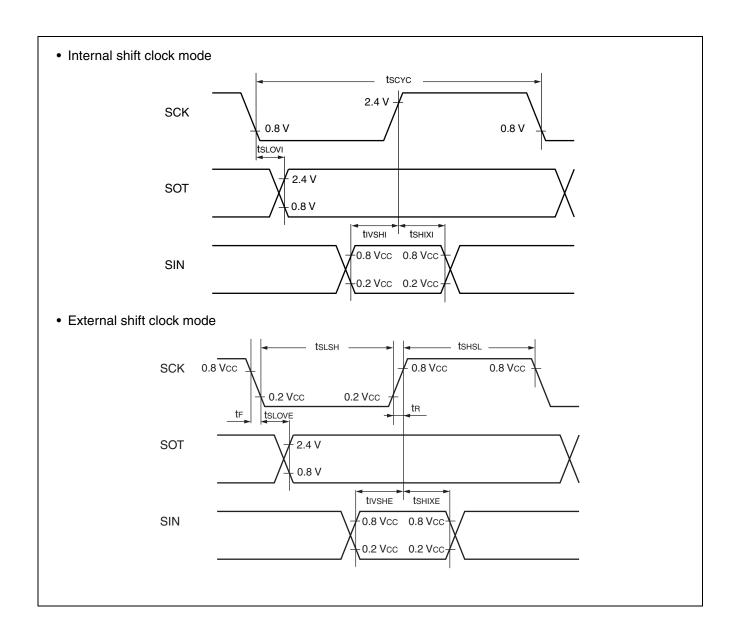
 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ AV}_{SS} = \text{V}_{SS} = 0.0 \text{ V}, \text{TA} = -40 \text{ °C to } + 105 \text{ °C})$

Dovometer	Sym-	Din nama	Condition	Va	lue	Unit
Parameter	bol	Pin name	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 tмськ*³	_	ns
$SCK \downarrow \to SOT$ delay time	tslovi	SCK, SOT	Internal clock operation output pin :	– 95	+95	ns
Valid SIN → SCK ↑	tıvsнı	SCK, SIN	C _L = 80 pF + 1 TTL.	tмськ*3 + 190		ns
$SCK \uparrow \to valid \; SIN \; hold \; time$	tshixi	SCK, SIN		0		ns
Serial clock "L" pulse width	tslsh	SCK		3 tмськ*3 — tв	_	ns
Serial clock "H" pulse width	tshsl	SCK		tмськ*3 + 95		ns
$SCK \downarrow \to SOT$ delay time	tslove	SCK, SOT	External clock	_	2 tmcLK*3 + 95	ns
Valid SIN → SCK ↑	tivshe	SCK, SIN	operation output pin:	190	_	ns
$SCK \uparrow \to valid \; SIN \; hold \; time$	tshixe	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	tмськ*3 + 95		ns
SCK fall time	t⊧	SCK		_	10	ns
SCK rise time	t R	SCK		_	10	ns

^{*1 :} Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

^{*2 :} Serial clock delay function is used to delay half clock for the output signal of serial clock.

^{*3:} Refer to "(2) Source Clock / Machine Clock" for tmclk.



Sampling at the falling edge of sampling clock*1 and prohibited serial clock delay*2

(ESCR register : SCES bit = 1, ECCR register : SCDE bit = 0)

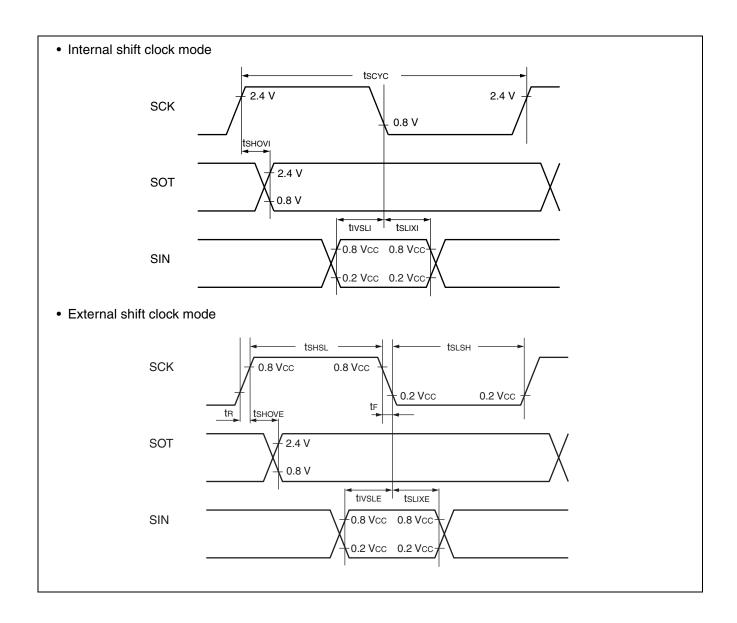
$$(Vcc = 5.0 \text{ V} \pm 10\%, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C to } + 105 \,^{\circ}\text{C})$$

Parameter	Sym-	Pin name	Condition	Va	lue	Unit
Parameter	bol	Fill Hallie	Condition	Min	Max	Oilit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³		ns
$SCK \uparrow \to SOT$ delay time	t shovi	SCK, SOT	Internal clock operation output pin :	– 95	+95	ns
Valid SIN → SCK \downarrow	tıvslı	SCK, SIN	C _L = 80 pF + 1 TTL.	tмськ*3 + 190		ns
$SCK \downarrow \to valid SIN hold time$	tslixi	SCK, SIN		0		ns
Serial clock "H" pulse width	t shsl	SCK		$3~t$ MCLK $^{*3}-t$ R		ns
Serial clock "L" pulse width	t slsh	SCK		tмськ*3 + 95		ns
$SCK \uparrow \to SOT$ delay time	t shove	SCK, SOT	External clock	_	2 tmclk*3 + 95	ns
Valid SIN $ ightarrow$ SCK \downarrow	tivsle	SCK, SIN	operation output pin :	190		ns
$SCK \downarrow \to validSINholdtime$	tslixe	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	tмськ*3 + 95		ns
SCK fall time	t⊧	SCK		_	10	ns
SCK rise time	t⊓	SCK		_	10	ns

^{*1 :} Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

^{*2:} Serial clock delay function is used to delay half clock for the output signal of serial clock.

^{*3:} Refer to "(2) Source Clock / Machine Clock" for tmclk.



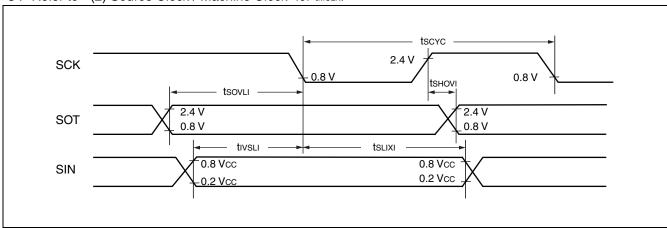
Sampling at the rising edge of sampling clock*1 and enabled serial clock delay*2

(ESCR register : SCES bit = 0, ECCR register : SCDE bit = 1)

$$(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 °C to + 105 °C)$$

Parameter	Sym-	Pin name	Condition	Valu	Unit	
raiametei	bol	Filitialile	Condition	Min	Max	Oilit
Serial clock cycle time	tscyc	SCK		5 t мськ*³	_	ns
$SCK \uparrow \to SOT delay time$	t shovi	SCK, SOT		- 95	+95	ns
Valid SIN \rightarrow SCK \downarrow	tıvslı	SCK, SIN	Internal clock operation output pin :	tмськ*3 + 190	_	ns
$\begin{array}{c} SCK \ \downarrow \to valid \ SIN \ hold \\ time \end{array}$	tslixi	SCK, SIN	C _L = 80 pF + 1 TTL.	0	_	ns
$SOT \to SCK \downarrow delay\ time$	tsovli	SCK, SOT			4 tmclk*3	ns

- *1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.
- *2: Serial clock delay function is used to delay half clock for the output signal of serial clock.
- *3: Refer to "(2) Source Clock / Machine Clock" for tmclk.



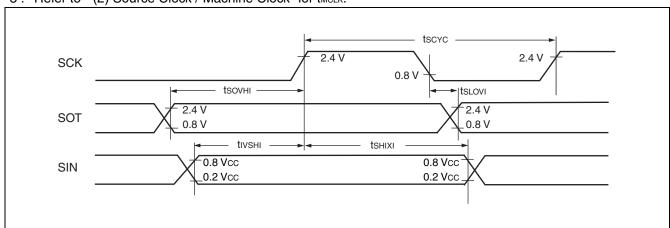
Sampling at the falling edge of sampling clock*1 and enabled serial clock delay*2

(ESCR register : SCES bit = 1, ECCR register : SCDE bit = 1)

$$(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 °C to + 105 °C)$$

Parameter	Sym-	Pin name	Condition	Valu	Unit		
Parameter	bol	Pili liaille	Condition	Min	Max		
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns	
$SCK \downarrow \to SOT$ delay time	tsLovi	SCK, SOT	Internal clock	– 95	+95	ns	
Valid SIN → SCK ↑	t ıvshı	SCK, SIN	operating output pin :	tмськ*3 + 190	_	ns	
$SCK \uparrow \to valid \; SIN \; hold \; time$	t shixi	SCK, SIN	$C_L = 80 \text{ pF} + 1 \text{ TTL}.$	0	_	ns	
$SOT \to SCK \uparrow delay time$	tsovні	SCK, SOT			4 tmclk*3	ns	

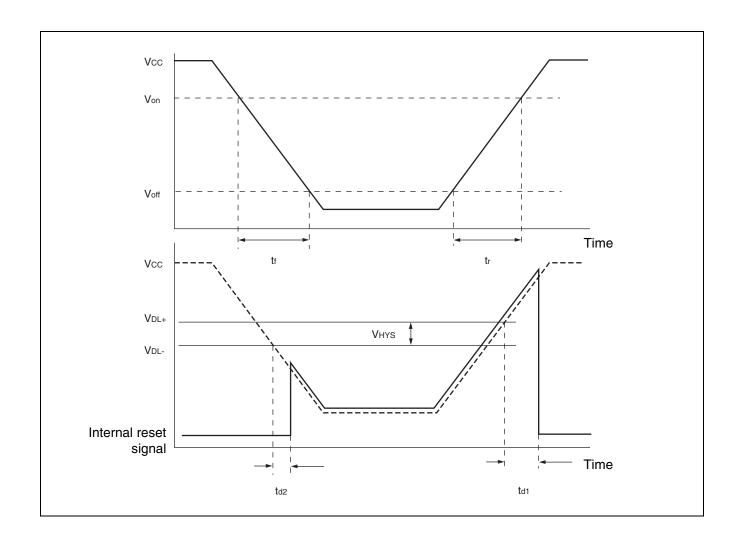
- *1: Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.
- *2: Serial clock delay function is used to delay half clock for the output signal of serial clock.
- *3: Refer to "(2) Source Clock / Machine Clock" for tmclk.



(8) Low voltage Detection

(AVss = Vss = 0.0 V, $T_A = -40$ °C to +105 °C)

Parameter	Sym-		Value		Unit	Remarks
Parameter	bol	Min	Тур	Max	Unit	nemarks
Release voltage	V_{DL^+}	2.52	2.70	2.88	V	At power-supply rise
Detection voltage	V _{DL}	2.42	2.60	2.78	V	At power-supply fall
Hysteresis width	V _{HYS}	70	100		mV	
Power-supply start voltage	Voff	_	_	2.3	V	
Power-supply end voltage	Von	4.9	_	_	V	
Power-supply voltage		0.3	_	_	μs	Slope of power supply that reset re- lease signal generates
change time (at power supply rise)	tr	_	3000	_	μs	Slope of power supply that reset release signal generates within rating (V _{DL+})
Power-supply voltage		300	_	_	μs	Slope of power supply that reset detection signal generates
change time (at power supply fall)	t f	_	300	_	μs	Slope of power supply that reset detection signal generates within rating (V _{DL} -)
Reset release delay time	t d1	_	_	400	μs	
Reset detection delay time	t d2	—	_	30	μs	
Consumption current	ILVD	_	38	50	μА	Consumption current of low voltage detection circuit only



(9) Clock Supervisor Clock

(Vcc = AVcc = 5 V \pm 10%, AVss = Vss = 0.0 V, Ta = -40 °C to +105 °C)

Parameter	Sym-		Value		Unit	Remarks	
Parameter	bol	Min	Тур Мах		Ullit	nemarks	
Oscillation frequency	fоит	50	100	200	kHz		
Oscillation start time	twk	_	_	10	μs		
Current consumption	Icsv	_	20	36	μА	Current consumption of built-in CR oscillator at 100 kHz oscillation	

5. A/D Converter

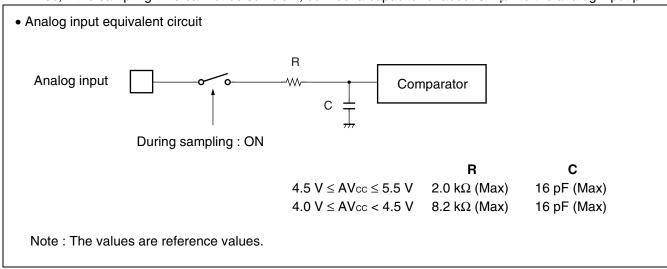
(1) A/D Converter Electrical Characteristics

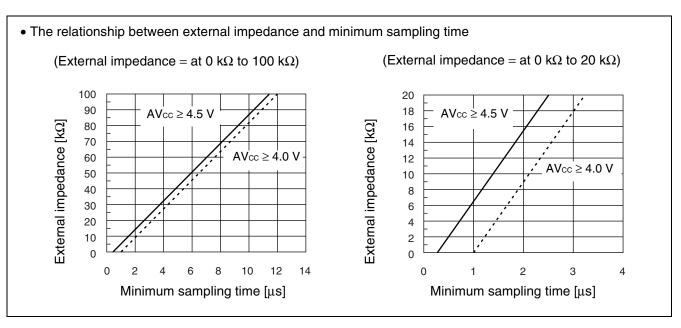
(AVcc = Vcc = 4.0 V to 5.5 V, AVss = Vss = 0.0 V, T_A = -40 °C to +105 °C)

Dawamatan	Cumbal		Value		l lm!t	Domonico	
Parameter	Symbol	Min	Тур	Max	Unit	Remarks	
Resolution		_	_	10	bit		
Total error		- 3.0	_	+ 3.0	LSB		
Linearity error		_	- 2.5	_	+ 2.5	LSB	
Differential linear error		- 1.9	_	+ 1.9	LSB		
Zero transition voltage	Vот	AVss – 1.5 LSB	AVss + 0.5 LSB	AVss + 2.5 LSB	V		
Full-scale transition voltage	V _{FST}	AVcc – 4.5 LSB	AVcc – 1.5 LSB	AVcc + 0.5 LSB	V		
Compare time		0.9	_	16500	μs	4.5 V ≤ AVcc ≤ 5.5 V	
Compare ume		1.8	_	16500	μs	4.0 V ≤ AVcc < 4.5 V	
Sampling time		0.6	_	8	μs	$4.5 \text{ V} \le \text{ AVcc} \le 5.5 \text{ V},$ At external impedance < at $5.4 \text{ k}\Omega$	
Sampling time		1.2	_	8	μs	$4.0 \text{ V} \le \text{ AVcc} \le 4.5 \text{ V},$ At external impedance < at 2.4 k Ω	
Analog input current	Iain	- 0.3	—	+ 0.3	μΑ		
Analog input voltage	Vain	AVss	_	AVcc	V		

(2) Notes on Using A/D Converter

- External impedance of analog input and its sampling time
 - A/D converter with sample and hold circuit. If the external impedance is too high to keep sufficient sampling
 time, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting
 A/D conversion precision. Therefore to satisfy the A/D conversion precision standard, consider the relationship
 between the external impedance and minimum sampling time and either adjust the register value and operating
 frequency or decrease the external impedance so that the sampling time is longer than the minimum value.
 Also, if the sampling time cannot be sufficient, connect a capacitor of about 0.1 μF to the analog input pin.





• Errors

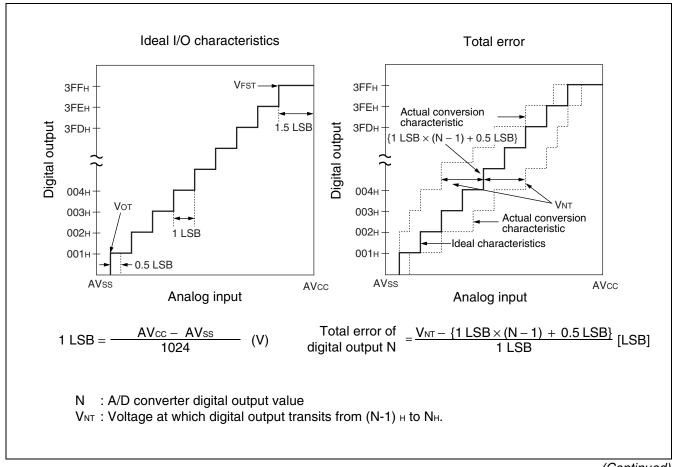
As IAVcc - AVssl becomes smaller, values of relative errors grow larger.

(3) Definition of A/D Converter Terms

Resolution

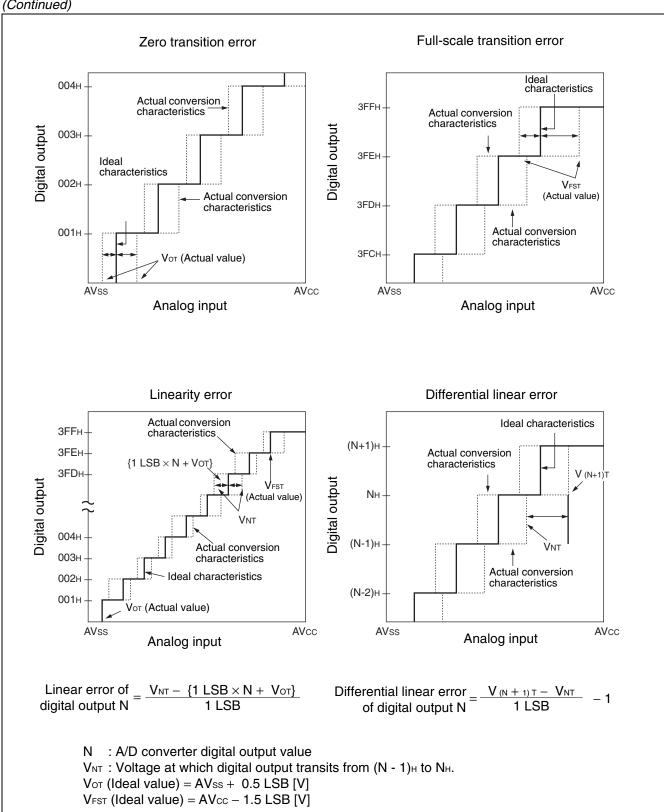
The level of analog variation that can be distinguished by the A/D converter. When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

- Linearity error (unit : LSB)
 - The deviation between the value along a straight line connecting the zero transition point ("00 0000 0000" \leftarrow \rightarrow "00 0000 0001") of a device and the full-scale transition point ("11 1111 1111" \leftarrow \rightarrow "11 1111 1110") compared with the actual conversion values obtained.
- Differential linear error (Unit : LSB)
 Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.
- Total error (unit: LSB)
 Difference between actual and theoretical values, caused by a zero transition error, full-scale transition error, linearity error, quantum error, and noise.



(Continued)

(Continued)



6. Flash Memory Program/Erase Characteristics

Parameter	Value			Unit	Remarks
Parameter	Min	Тур	Max	Ullit	nemarks
Chip erase time	_	1.0*1	15.0*2	S	Excludes 00 _H programming prior erasure.
Byte programming time	_	32	3600	μs	Excludes system-level overhead.
Erase/program cycle	10000	_	_	cycle	
Power supply voltage at erase/ program	4.5	_	5.5	V	
Flash memory data retention time	20*3		_	year	Average T _A = +85 °C

^{*1 :} $T_A = +25$ °C, $V_{CC} = 5.0$ V, 10000 cycles

^{*2 :} $T_A = +85$ °C, $V_{CC} = 4.5$ V, 10000 cycles

 $^{^*3}$: This value comes from the technology qualification (using Arrhenius equation to translate high temperature measurements into normalized value at +85 $^\circ$ C) .

■ MASK OPTION

No.	Part number	MB95136MB	MB95F133MBS MB95F133NBS MB95F133JBS MB95F134MBS MB95F134NBS MB95F134JBS MB95F136MBS MB95F136NBS MB95F136JBS	MB95F133MBW MB95F133NBW MB95F133JBW MB95F134MBW MB95F134NBW MB95F134JBW MB95F136MBW MB95F136NBW MB95F136JBW	MB95FV100D-103
	Specifying procedure	Specify when ordering MASK	Setting disabled	Setting disabled	Setting disabled
	Clock mode select Single-system clock mode Dual-system clock mode	selectable	Single-system clock mode	Dual-system clock mode	Changing by the switch on MCU board
2	Low voltage detection reset* • With low voltage detection reset • Without low voltage detection reset	Specify when ordering MASK	Specified by part number	Specified by part number	Change by the switch on MCU board
3	Clock supervisor* • With clock supervisor • Without clock supervisor	Specify when ordering MASK	Specified by part number	Specified by part number	Change by the switch on MCU board
4	Reset output* • With reset output • Without reset output	Not selectable	Not selectable	Not selectable	MCU board switch set as following; • With supervisor: Without reset output • Without supervisor: With reset output
1 5	Oscillation stabilization wait time	Fixed to oscillation stabilization wait time of $(2^{14} - 2)$ /Fch	Fixed to oscillation stabilization wait time of (2 ¹⁴ – 2) /FcH	Fixed to oscillation stabilization wait time of (2 ¹⁴ – 2) /FcH	Fixed to oscillation stabilization wait time of $(2^{14}-2)$ /FcH

^{*:} Refer to table below about clock mode select, low voltage detection reset, clock supervisor select and reset output.

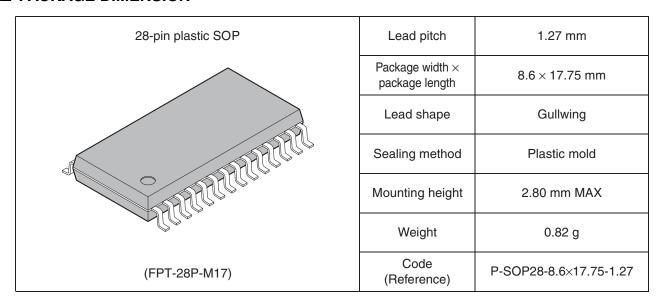
Part number	Clock mode select	Low-voltage detection reset	Clock supervisor	Reset output*
MDOSTOOMB	Single - system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No
MB95136MB	Dual - system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No
MB95F133MBS		No	No	Yes
MB95F133NBS		Yes	No	Yes
MB95F133JBS		Yes	Yes	No
MB95F134MBS	Single - system	No	No	Yes
MB95F134NBS		Yes	No	Yes
MB95F134JBS		Yes	Yes	No
MB95F136MBS		No	No	Yes
MB95F136NBS		Yes	No	Yes
MB95F136JBS		Yes	Yes	No
MB95F133MBW		No	No	Yes
MB95F133NBW		Yes	No	Yes
MB95F133JBW		Yes	Yes	No
MB95F134MBW		No	No	Yes
MB95F134NBW	Dual - system	Yes	No	Yes
MB95F134JBW		Yes	Yes	No
MB95F136MBW		No	No	Yes
MB95F136NBW		Yes	No	Yes
MB95F136JBW		Yes	Yes	No
MB95FV100D-103	Single - system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No
	Dual - system	No	No	Yes
		Yes	No	Yes
		Yes	Yes	No

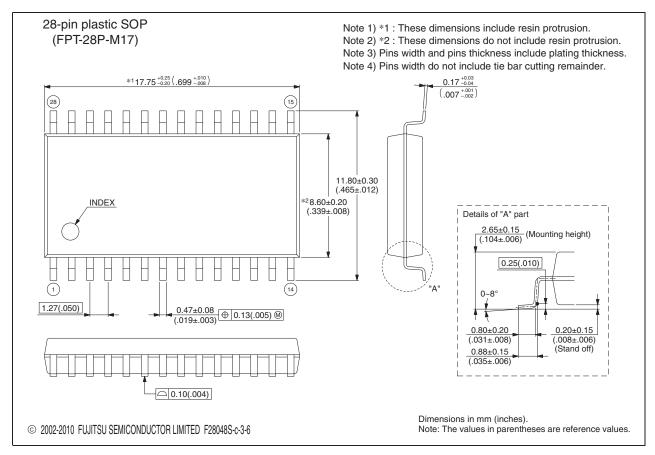
^{*:} If the clock supervisor is selected, reset output is always disabled.

■ ORDERING INFORMATION

Part number	Package
MB95136MBPF MB95F133MBSPF MB95F133JBSPF MB95F134MBSPF MB95F134MBSPF MB95F134JBSPF MB95F136MBSPF MB95F136MBSPF MB95F136JBSPF MB95F133MBWPF MB95F133JBWPF MB95F134MBWPF MB95F134MBWPF MB95F134MBWPF MB95F134JBWPF MB95F136MBWPF MB95F136MBWPF MB95F136MBWPF	28-pin plastic SOP (FPT-28P-M17)
MB95136MBPFV MB95F133MBSPFV MB95F133JBSPFV MB95F133JBSPFV MB95F134MBSPFV MB95F134NBSPFV MB95F134JBSPFV MB95F136MBSPFV MB95F136JBSPFV MB95F133MBWPFV MB95F133NBWPFV MB95F133JBWPFV MB95F134MBWPFV MB95F134MBWPFV MB95F134MBWPFV MB95F136MBWPFV MB95F136MBWPFV MB95F136MBWPFV MB95F136MBWPFV	30-pin plastic SSOP (FPT-30P-M02)
MB2146-303A-E (MB95FV100D-103PBT)	MCU board (224-pin plastic PFBGA) (BGA-224P-M08)

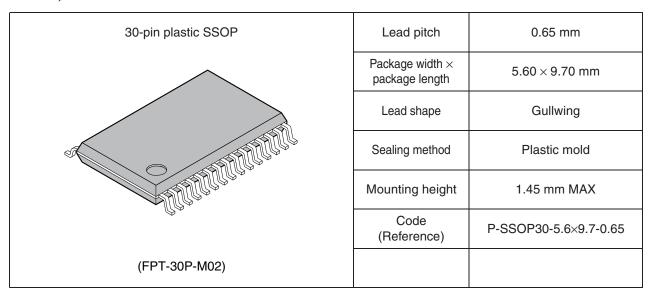
■ PACKAGE DIMENSION

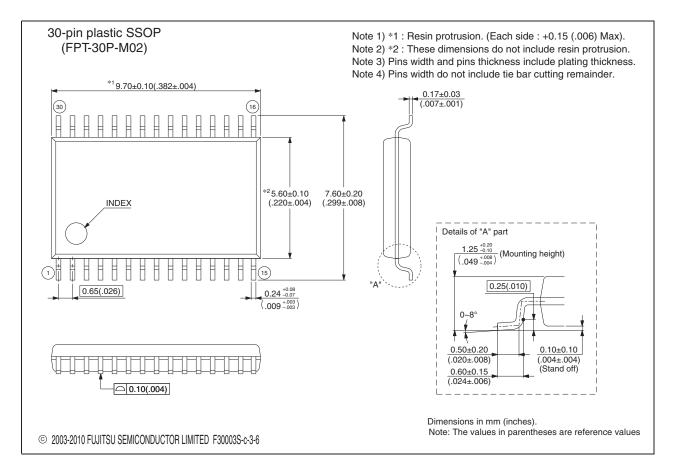




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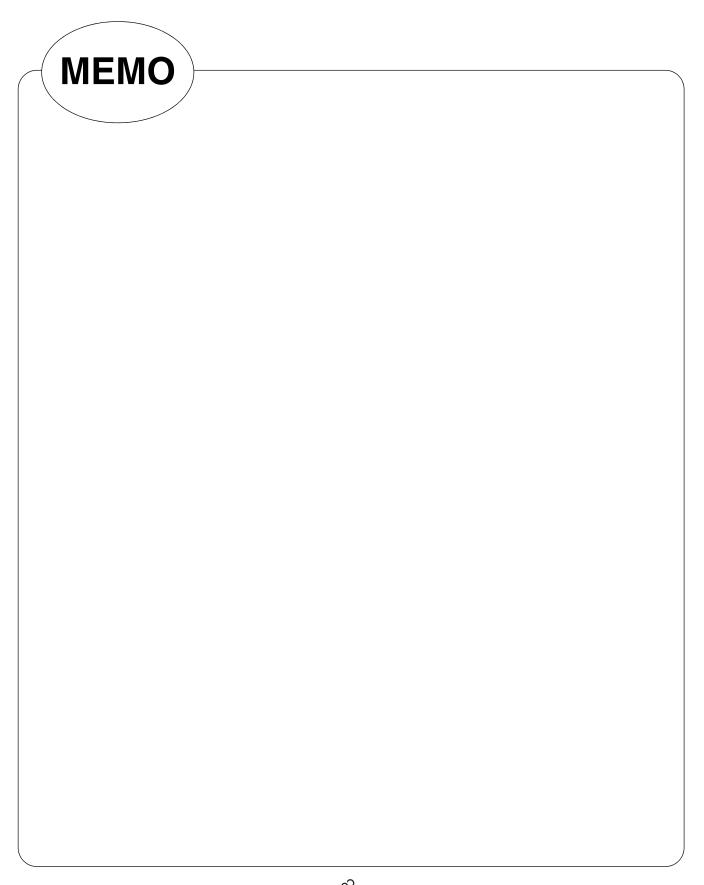




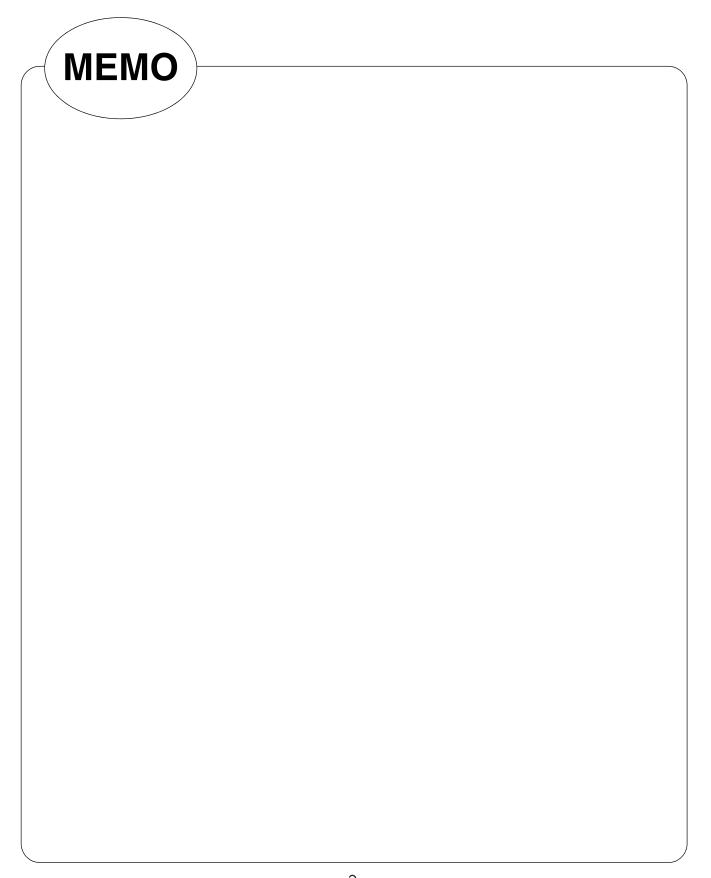
■ MAJOR CHANGES IN THIS EDITION

A change on a page is indicated by a vertical line drawn on the left side of that page.

Page	Section	Change Results
2	■ FEATURES	Added "• Power-on reset".
4	■ PRODUCT LINEUP	Added the parameter "Power-on reset".
		Changed the reset output of MB95136MB. Yes \rightarrow Not selectable
29	■ ELECTRICAL CHARACTERISTICS 1. Absolute Maximum Ratings	Changed the maximum rating of the operating temperature. $85 \rightarrow 105$
40	40 ■ ELECTRICAL CHARACTERISTICS 4. AC Characteristics (2) Source Clock / Machine Clock	Added MB95136MB to the part numbers in "• Operating voltage - Operating frequency".
41		Changed the x-axis of the graph in " • Main PLL operation frequency". Machine clock frequency (FMP) → Main oscillation (FCH)
60	■ MASK OPTION	Changed the "Reset output" of the products listed below to "Not selectable". MB95136MB MB95F133MBS MB95F133NBS MB95F133JBS MB95F134MBS MB95F134NBS MB95F136MBS MB95F136MBS MB95F136NBS MB95F136JBS MB95F133MBW MB95F133JBW MB95F134MBW MB95F134MBW MB95F134MBW MB95F134DBW MB95F136MBW MB95F136MBW MB95F136MBW MB95F136NBW MB95F136NBW MB95F136JBW
61		Added the following note. If the clock supervisor is selected, reset output is always disabled.



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